

RX140 Group

RX140 HMI sample program with touch keys and LCD

Introduction

This application note describes a sample program to realize touch function and serial LCD display using Renesas Starter Kit for RX140 and separately sold LCD module.

The sample program described in this application note is configured using the following libraries.

LCD Display : Embedded GUI software emWin (hereinafter referred to as “emWin”)

Target Device

RX140 Group

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

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1. Outline

This application note describes a sample program to realize touch function and serial LCD display using Renesas Starter Kit for RX140 and separately sold LCD module.

The touch buttons and touch slider and LCD (240 x 320) module in Renesas Starter Kit for RX140 are used to control the configuration and display of the UI, which imitates a microwave oven.

The system configuration is shown below.

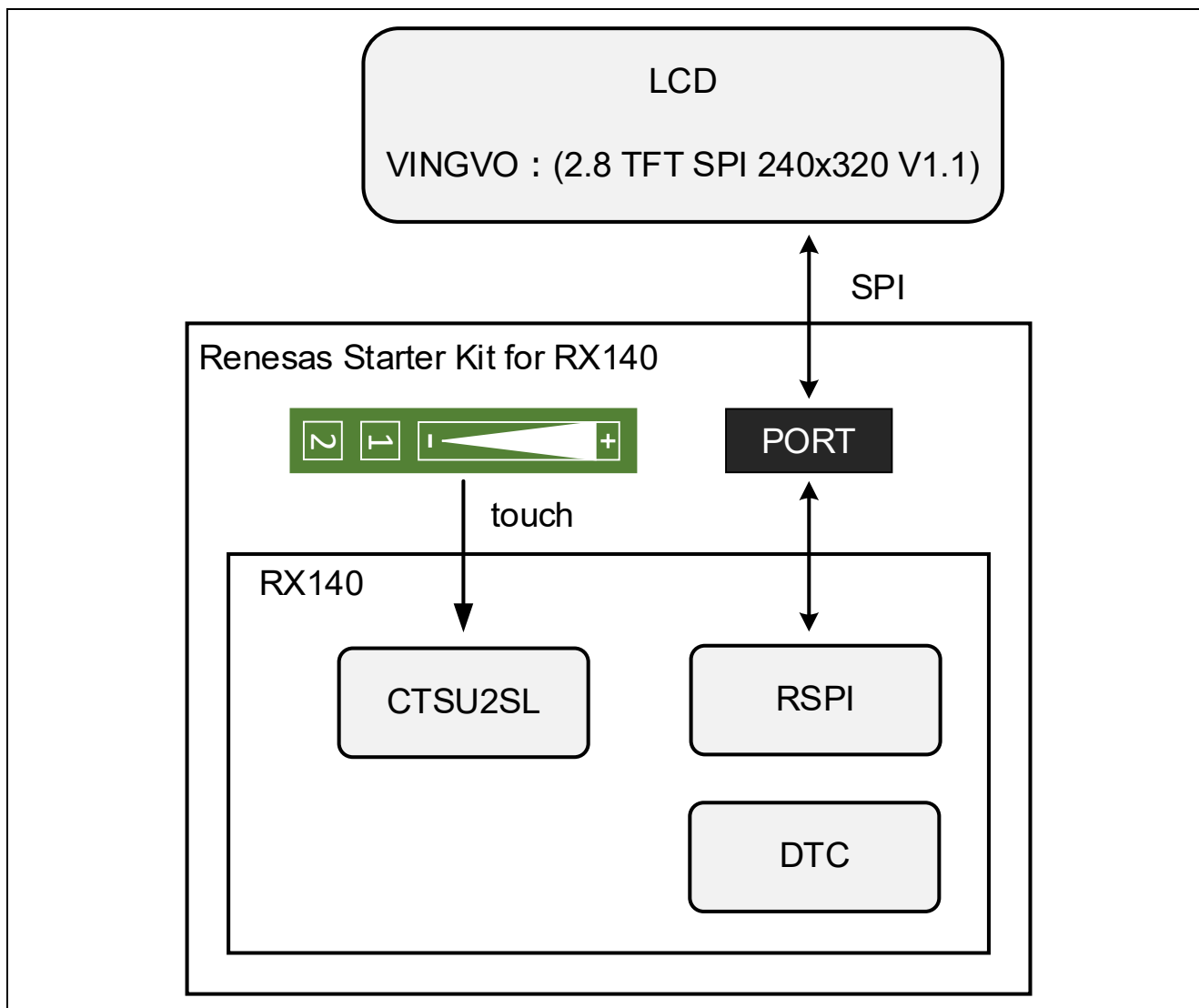


Figure 1-1 System configuration

The system configuration is shown below.

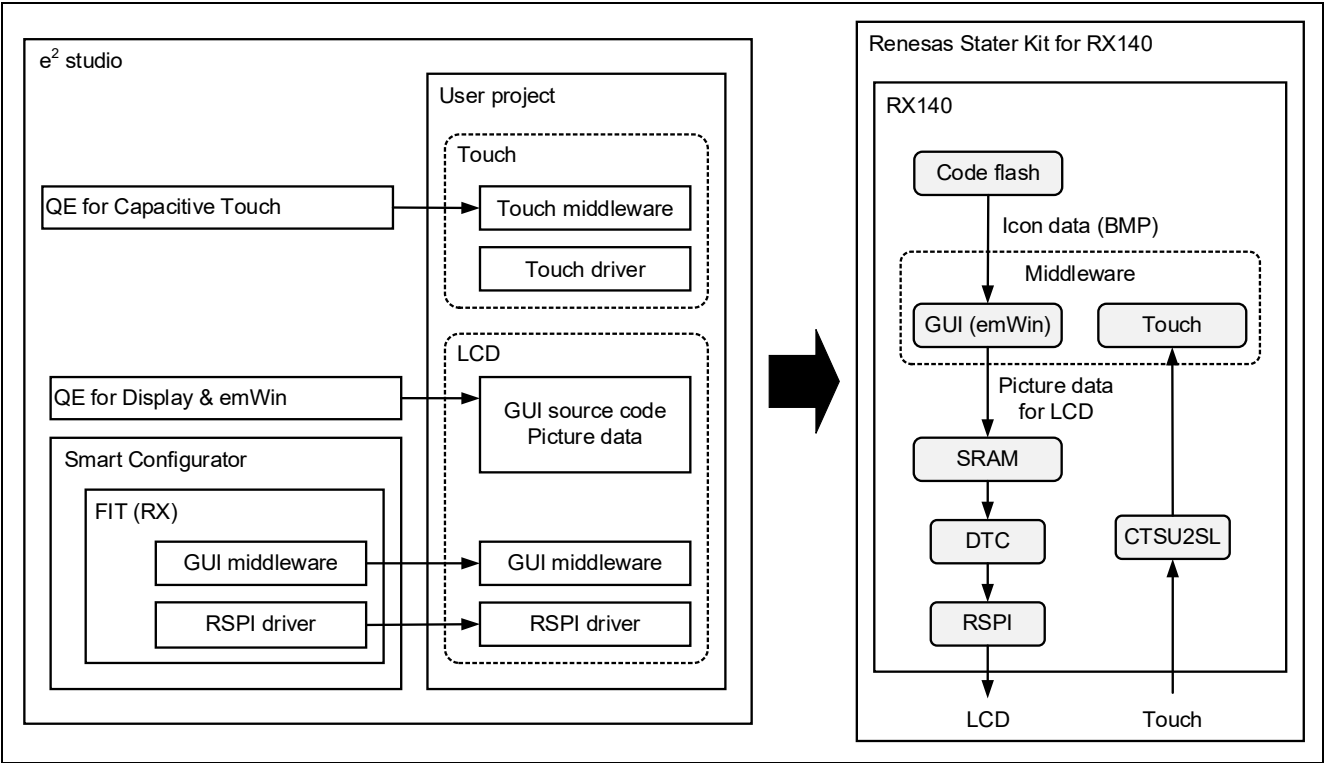


Figure 1-2 Software configuration

2. Operation Confirmation Conditions

The operation of the sample program has been confirmed under the following conditions.

Table 2-1 Operation Confirmation Conditions

Item	Contents
MCU used	R5F51406BDFN (RX140 Group)
Operating frequency	Operating frequency (ICLK) : 48MHz Peripheral operating frequency (PCLKB) : 24MHz
Operating voltage	5V
Integrated development	Renesas Electronics e ² studio Version 2023-01 (23.1.0)
C compiler	Renesas Electronics C/C++ Compiler Package for RX Family V3.05.00
	Compiler option — optimize=max — speed — inline=800
Smart Configurator	RX 2.16.0
Board support package (r_bsp)	V7.21
Endian order	Little Endian
Operating mode	Single chip mode
Processor mode	Super visor mode
Sample code version	V1.00
Emulator	E2 Emulator Lite
Board used	Renesas Starter Kit for RX140 (RTK551406BS00000BE)

Table 2-2 Operation Confirmation Conditions (LCD)

Item	Contents
LCD module	2.8 TFT SPI 240 x 320 serial port module

3. Hardware Preparation

3.1 Power supply setting

The power supply of Renesas Starter Kit for RX140 used in this application note should be set as follows. For details, refer to "2.1 Requirements" in "RX140 Group Renesas Starter Kit for RX140 User's Manual".

Table 3-1 Power supply setting

J6	J7	R37	R44	Supply Source	Board_VCC UC_VCC
2-3 Shorted	1-2 Shorted	Don't care	Don't care	PWR / Unregulated_VCC / JA1-5V	5V

3.2 Connecting to LCD module

Connect Renesas Starter Kit for RX140 to the LCD module as follows

Table 3-2 Connection table

Renesas Starter Kit for RX140		2.8 TFT LCD Panel (J2)		Supplement
Pin number	Pin Name	Pin Number	Pin Name	
-	-	14	T_IRQ	OPEN
-	-	13	T_DO	OPEN
-	-	12	T_DIN	OPEN
-	-	11	T_CS	OPEN
-	-	10	T_CLK	OPEN
J2-3	MISO	9	MISO	-
9 (PMOD1)	GPIO/CS2	8	LED	-
J2-17	SCK	7	SCK	-
J2-4	MOSI	6	MOSI	-
10 (PMOD1)	GPIO/CS3	5	D/C	-
8 (PMOD1)	GPIO/RESET	4	RESET	-
1 (PMOD1)	CS	3	CS	-
5 (PMOD1)	GND	2	GND	-
6 (PMOD1)	3V3/5V	1	VCC	-

Renesas Starter Kit for RX140		2.8 TFT LCD Panel (J4)		Supplement
Pin number	Pin Name	Pin Number	Pin Name	
-	-	1	SD_CS	OPEN
-	-	2	SD_MOSI	OPEN
-	-	3	SD_MISO	OPEN
-	-	4	SD_SCK	OPEN

4. Sample Program

4.1 Demonstration Screen Flowchart

The demonstration screen flowchart of this sample program is shown below. For detail on each screen, refer to chapter 6.

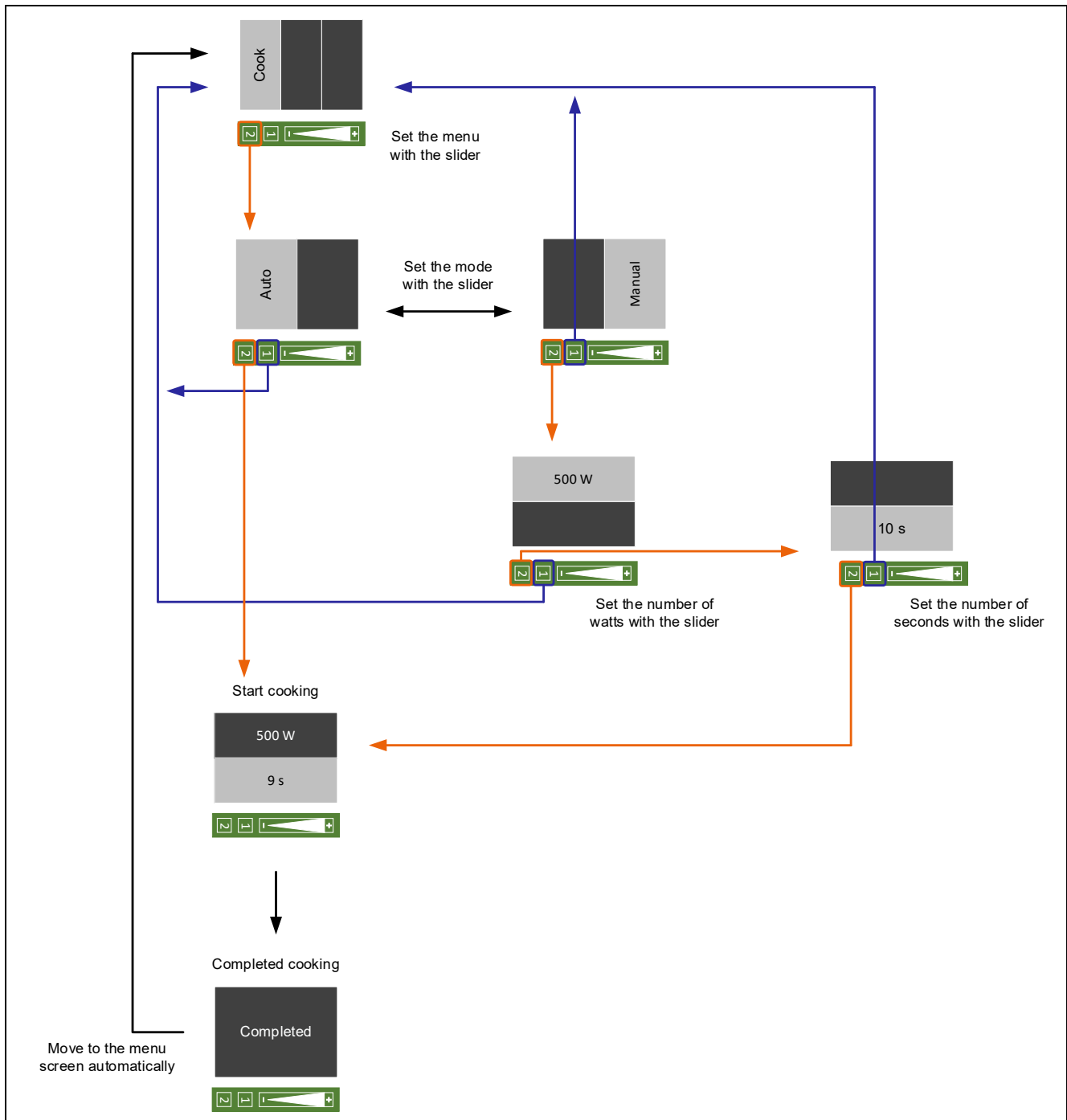


Figure 4-1 Flowchart of demonstration screen (Cook)

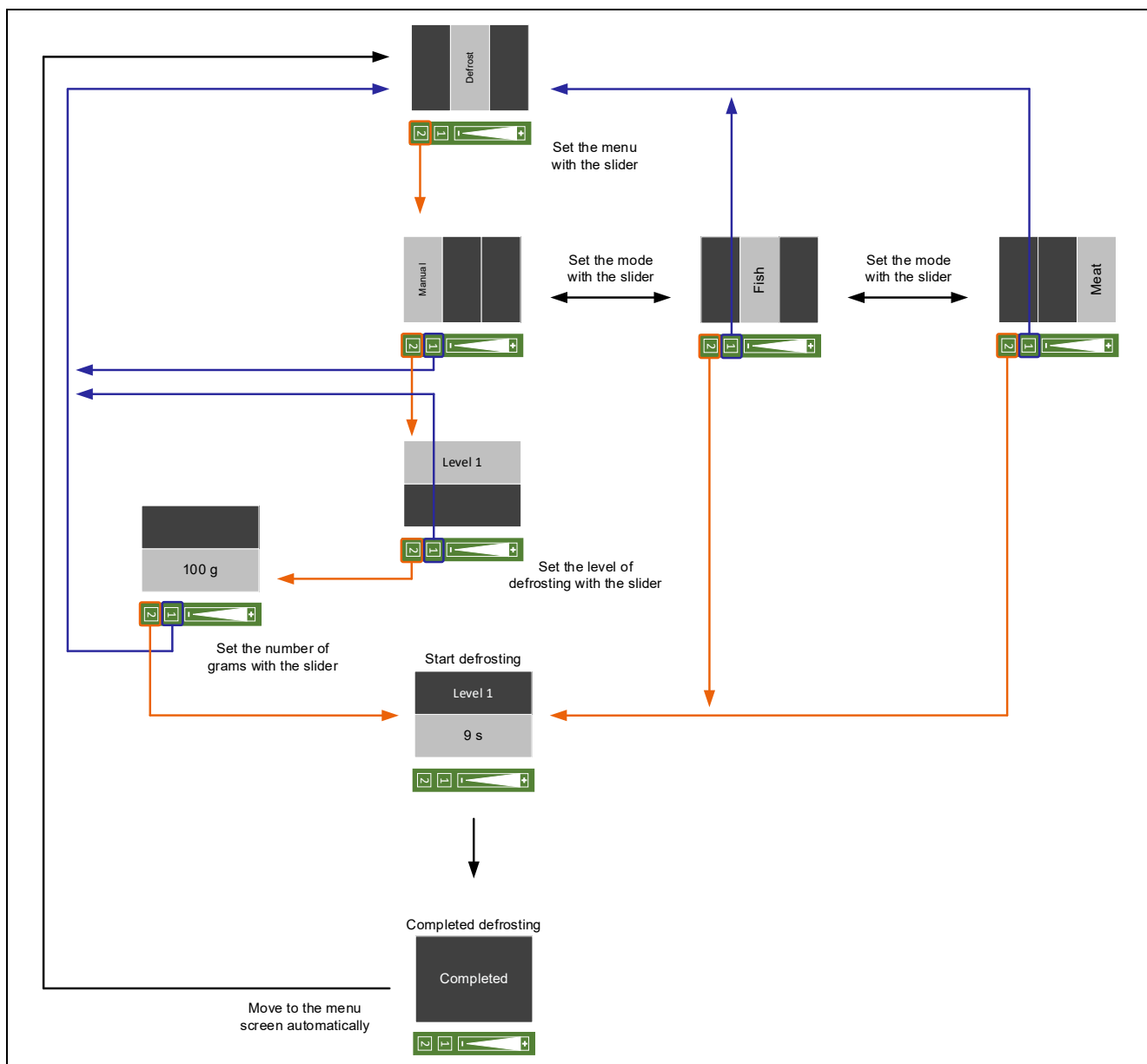


Figure 4-2 Flowchart of demonstration screen (Defrost)

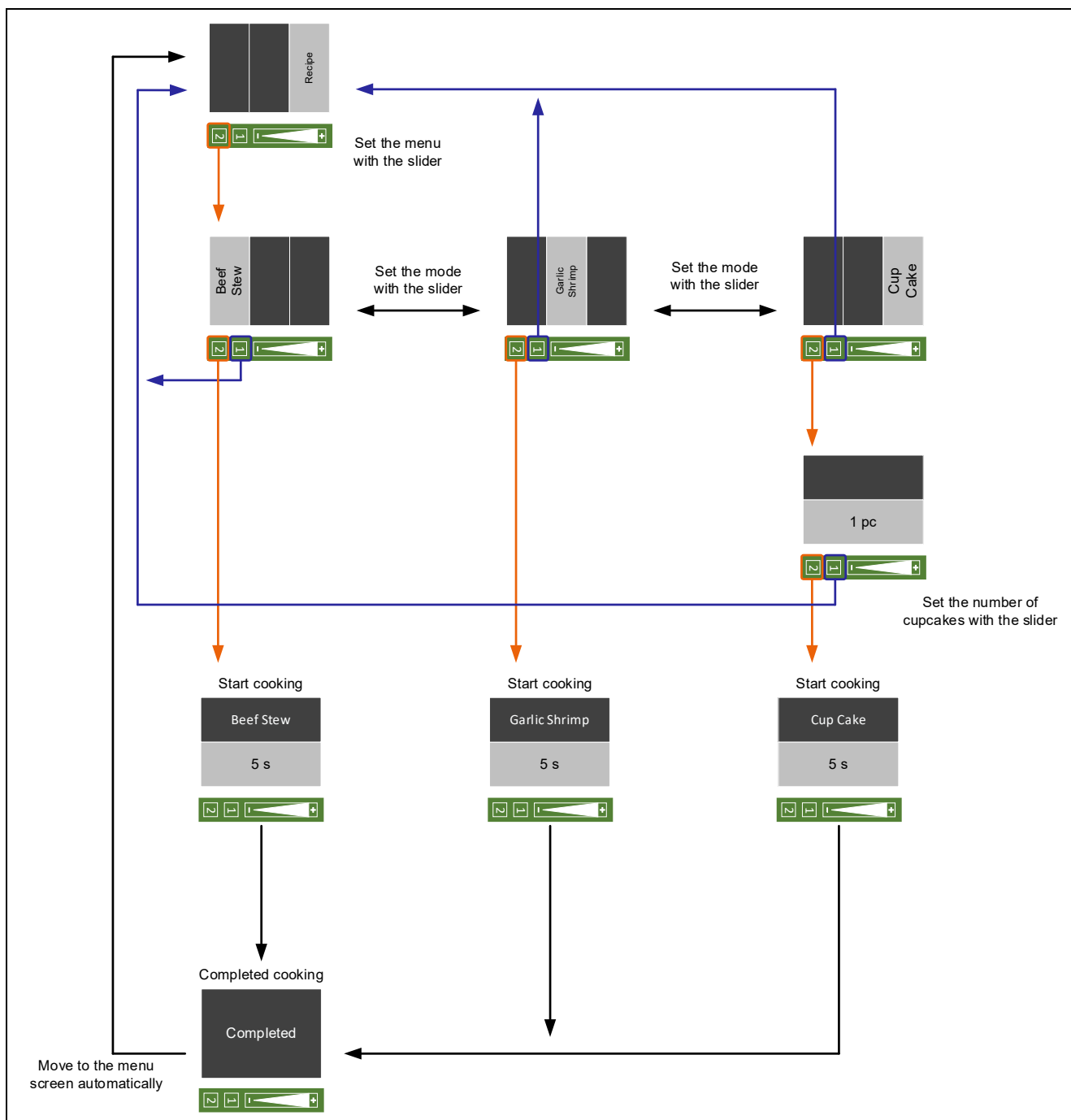


Figure 4-3 Flowchart of demonstration screen (Recipe)

4.2 Flowchart

4.2.1 Overall Flowchart

The overall flowchart is shown below.

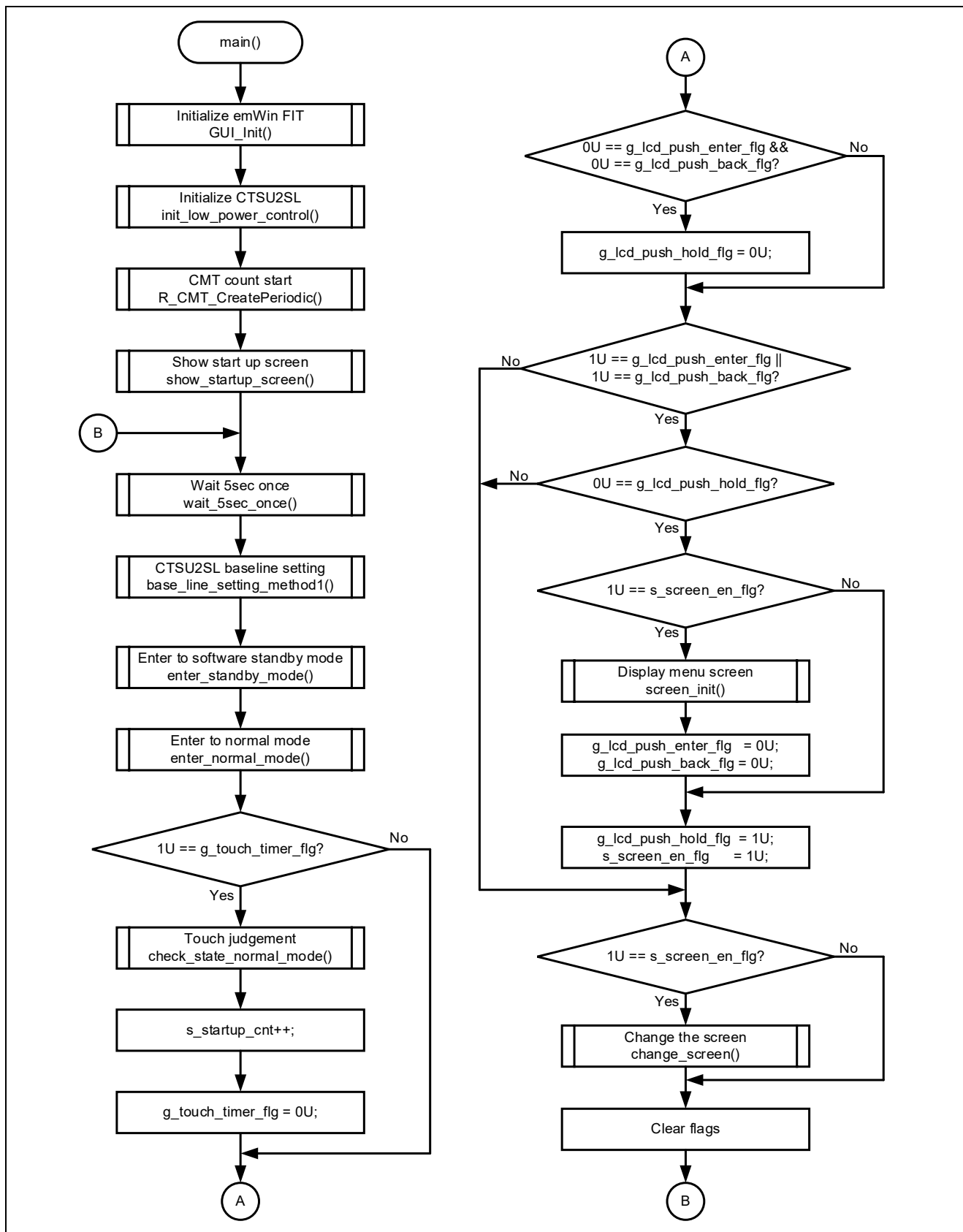


Figure 4-4 Overall flowchart

4.2.2 Processing at touch keys operation

The flowchart for touch keys operation is shown below.

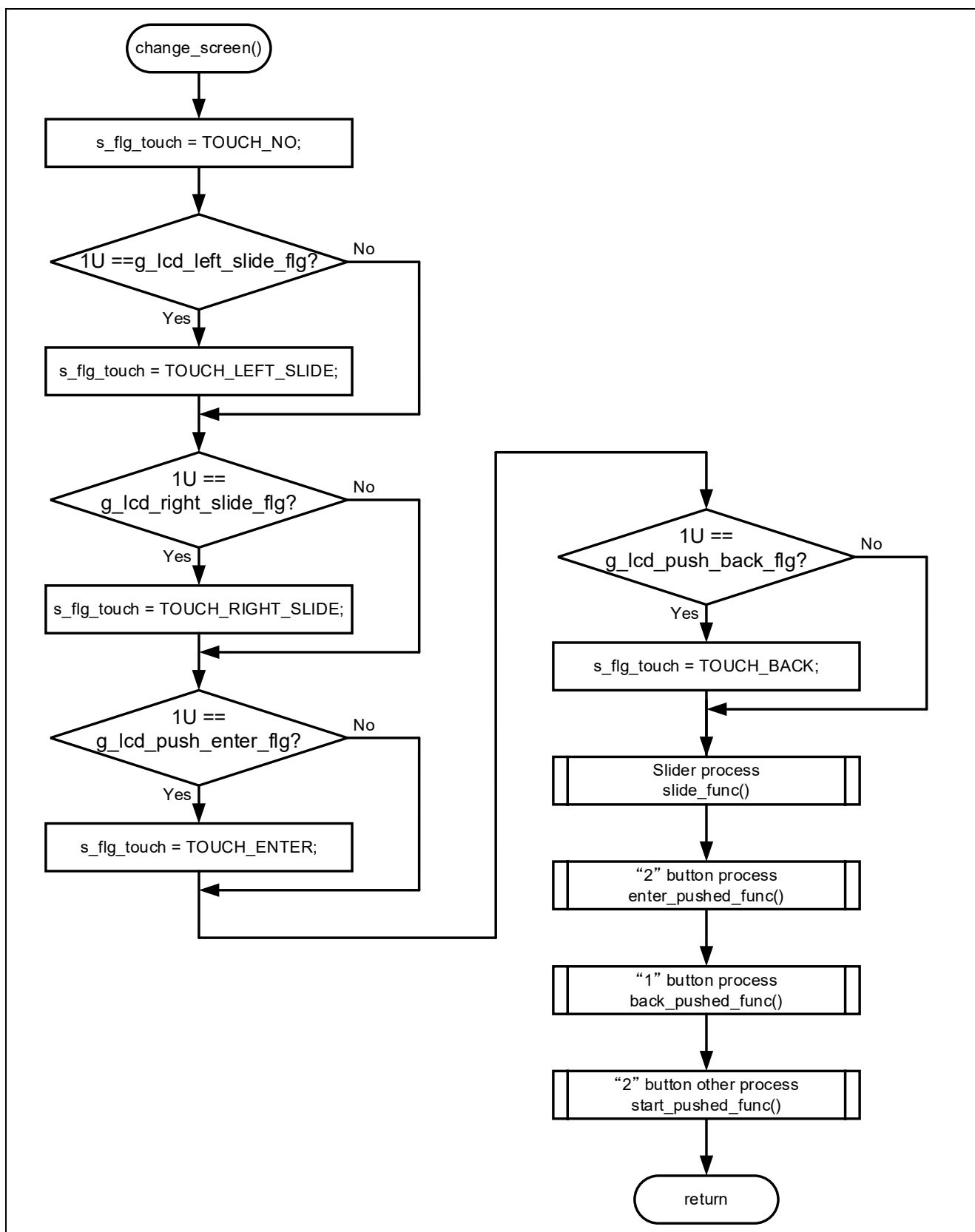


Figure 4-5 Flowchart for touch keys operation

4.2.3 Processing at touch slider operation

The flowchart for touch slider operation is shown below.

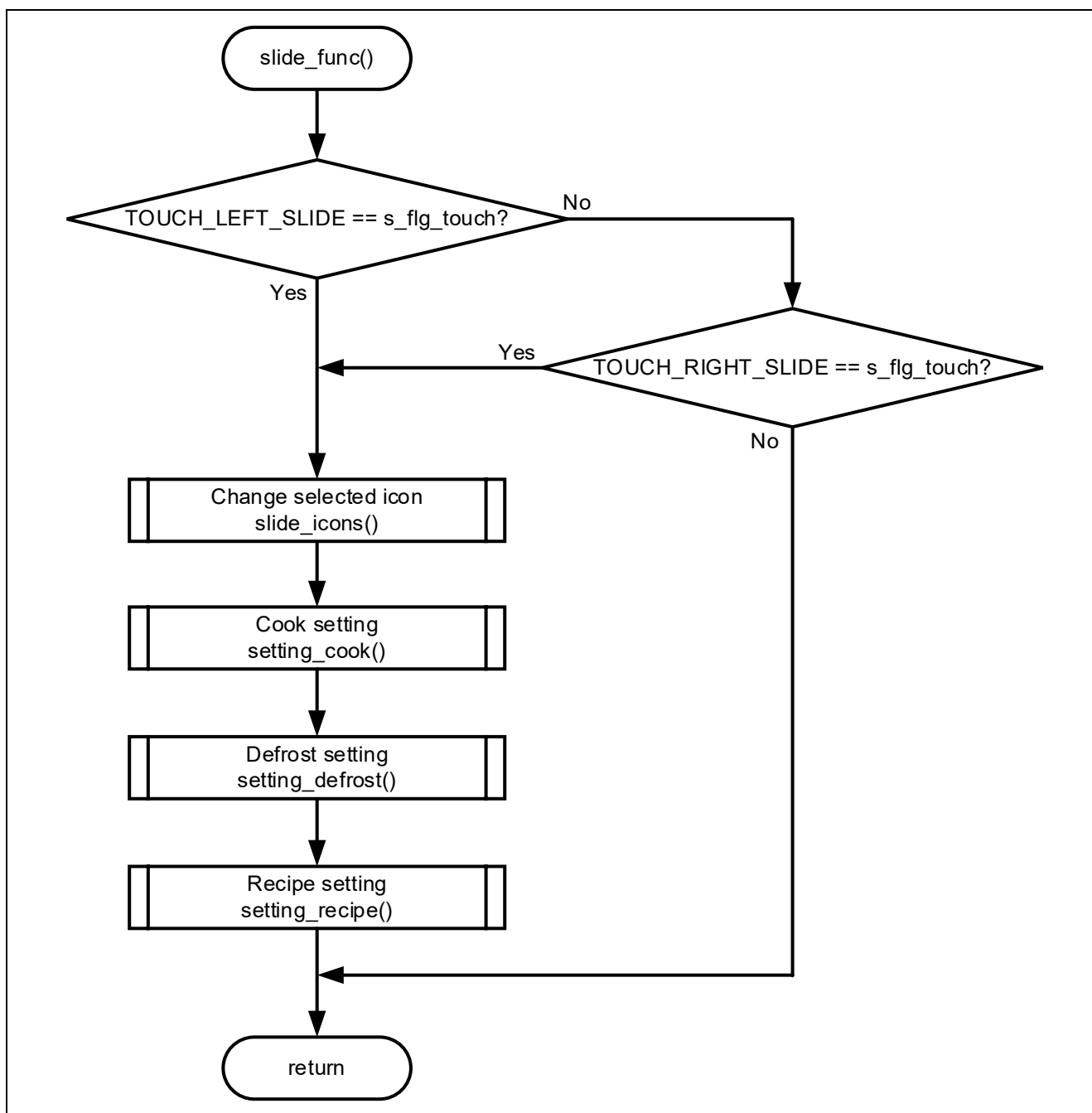


Figure 4-6 Flowchart for touch slider operation

4.2.4 Processing when the "1" button is touched

The flowchart when the "1" button is touched is shown below.

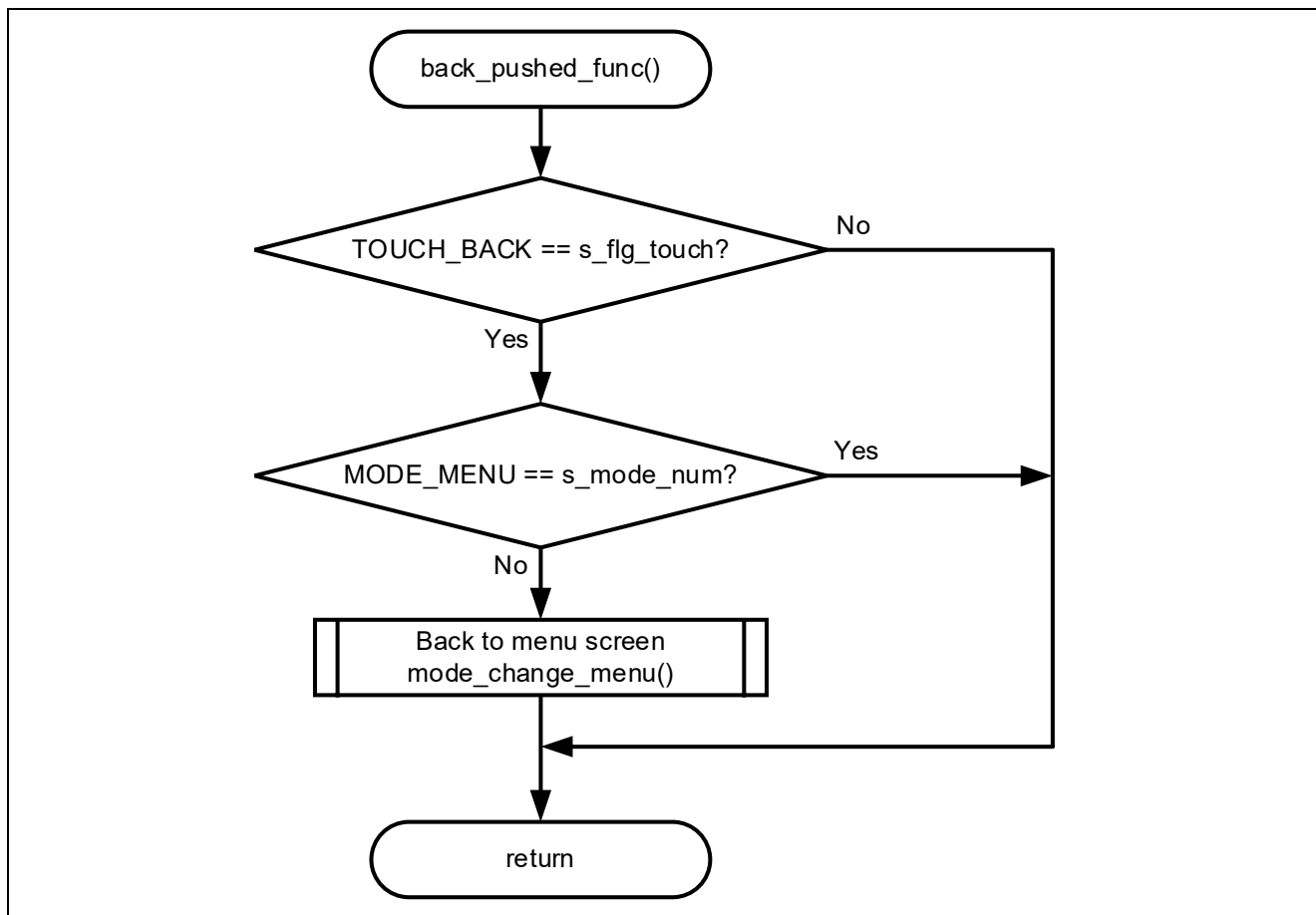


Figure 4-7 Flowchart when the "1" button is touched

4.2.5 Processing when the "2" button is touched (1)

The flowchart when the "2" button is touched is shown below.

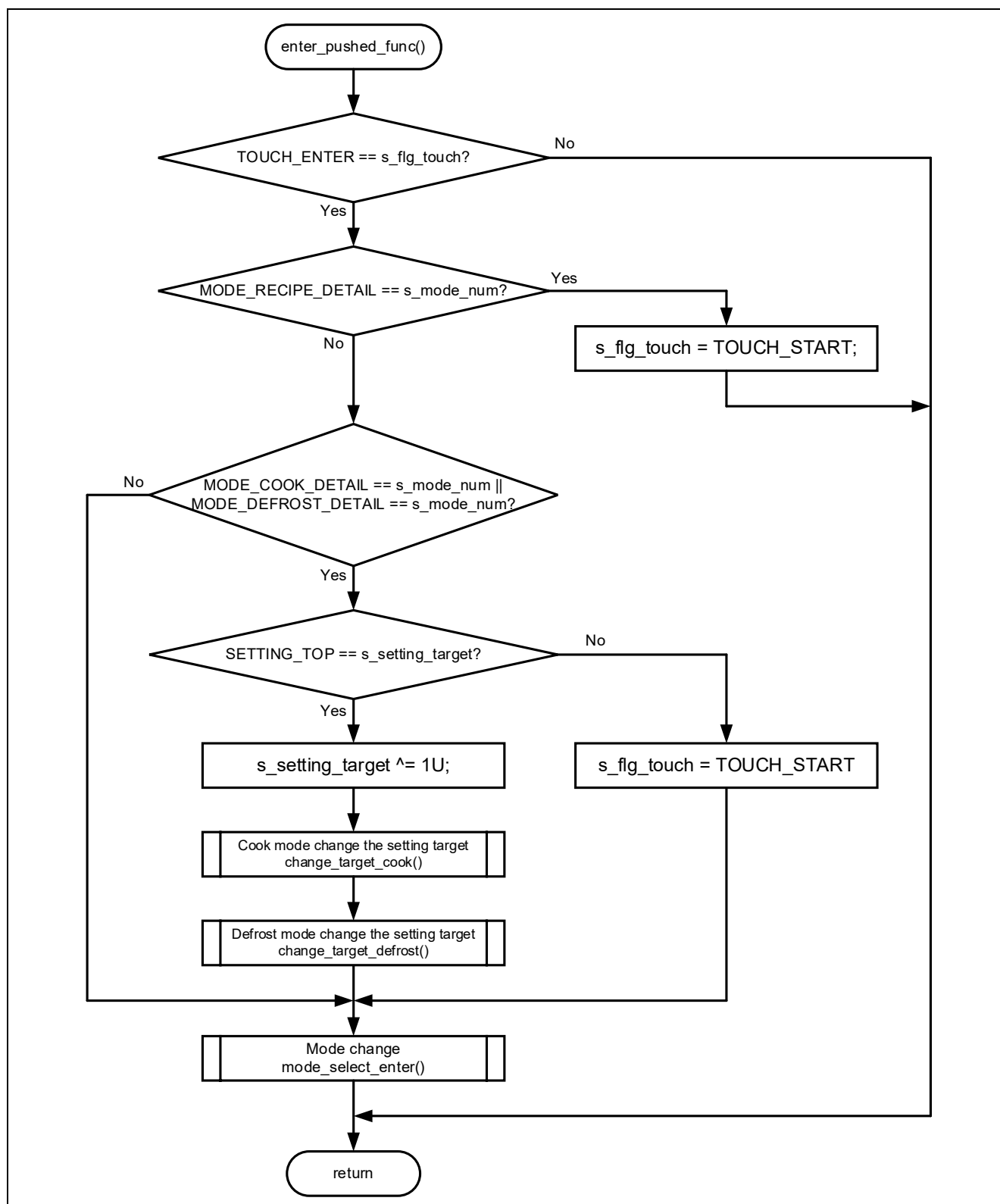


Figure 4-8 Flowchart when the "2" button is touched

4.2.6 Processing when the "2" button is touched (2)

The flowchart when the "2" button is touched is shown below.

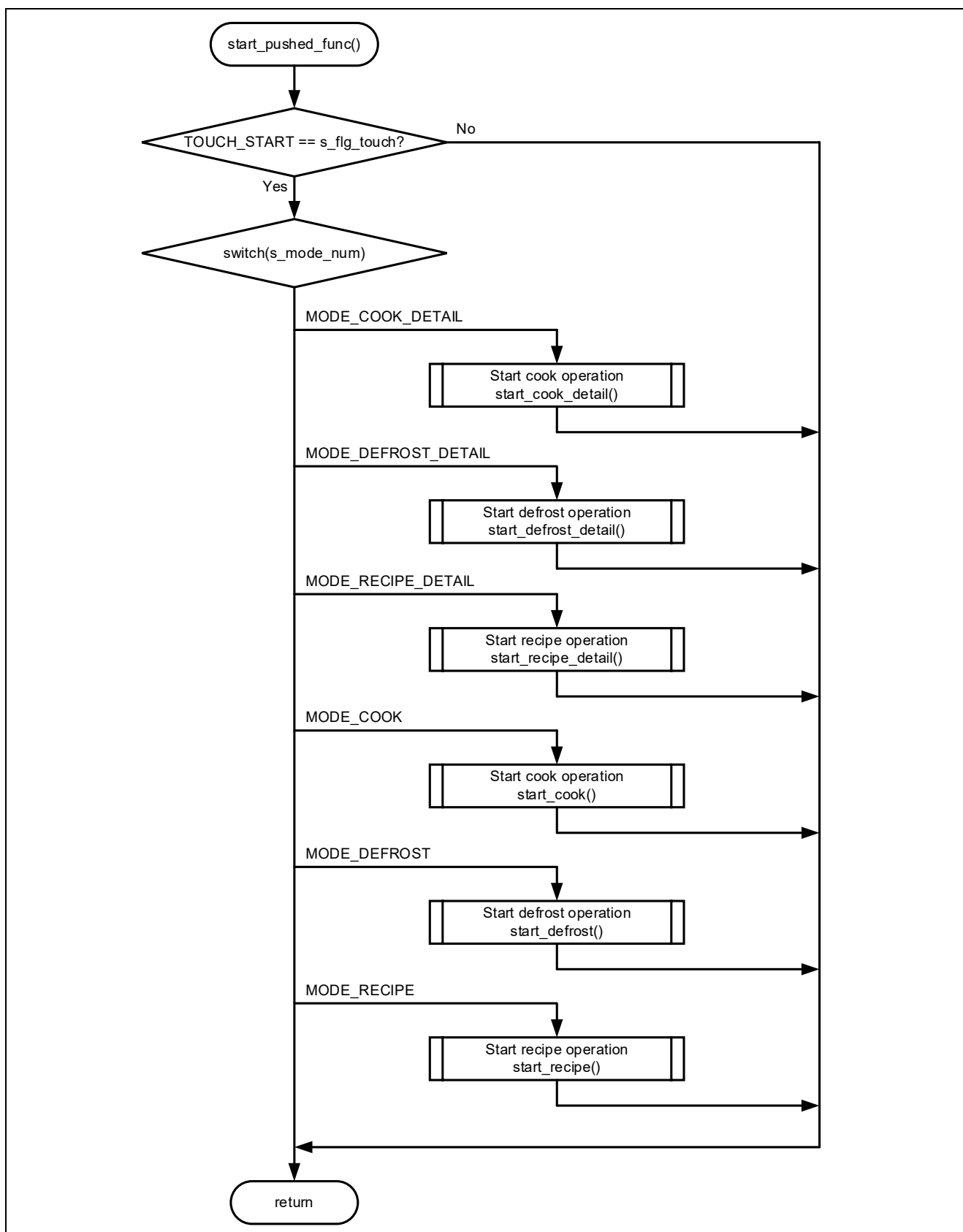


Figure 4-9 Flowchart when the "2" button is touched

4.2.7 Processing of CTSU2SL initialization

The flowchart of CTSU2SL initialization is shown below.

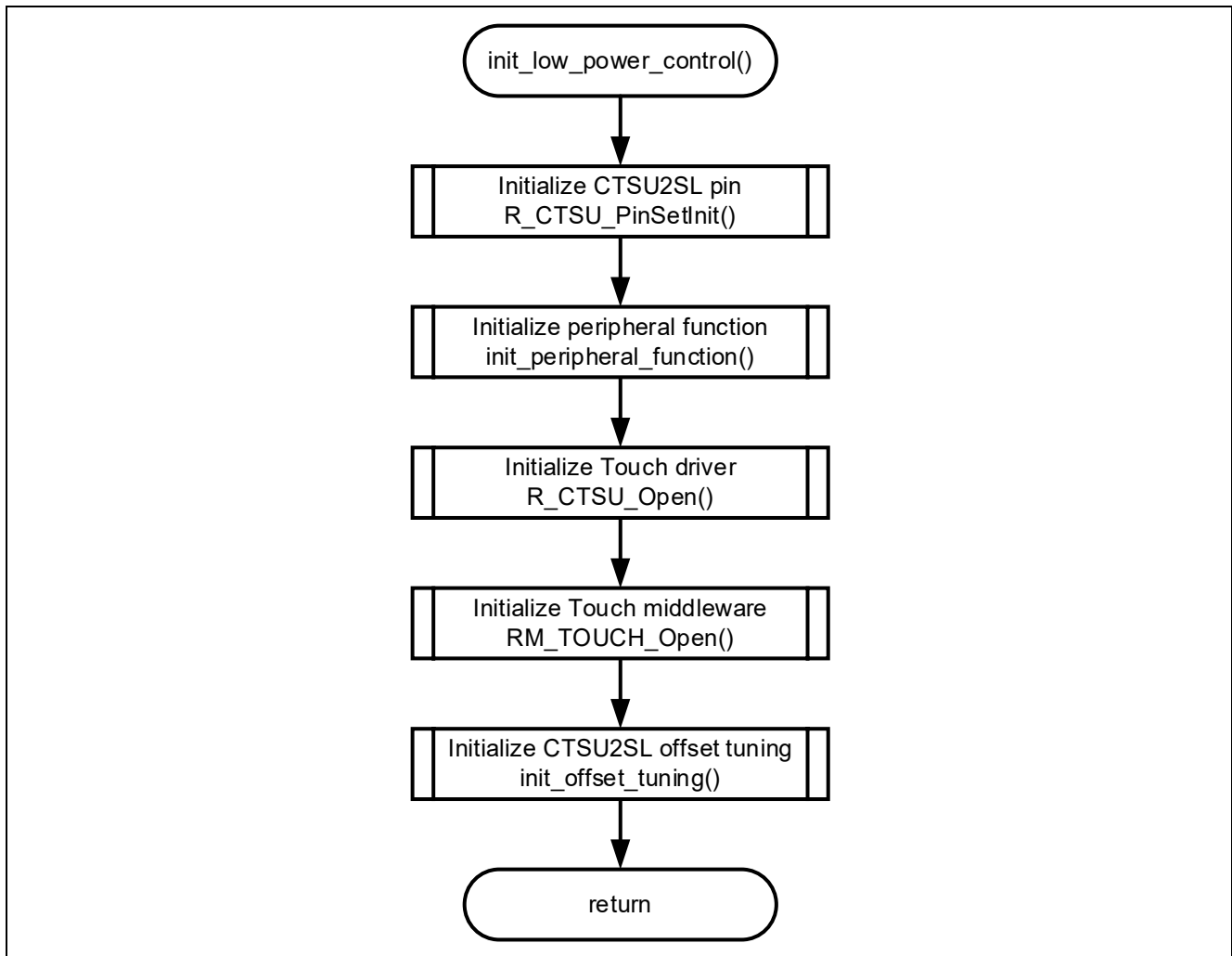


Figure 4-10 Flowchart of CTSU2SL initialization

4.2.8 Processing of CTSU2SL baseline settings

The flowchart of CTSU2SL baseline settings is shown below.

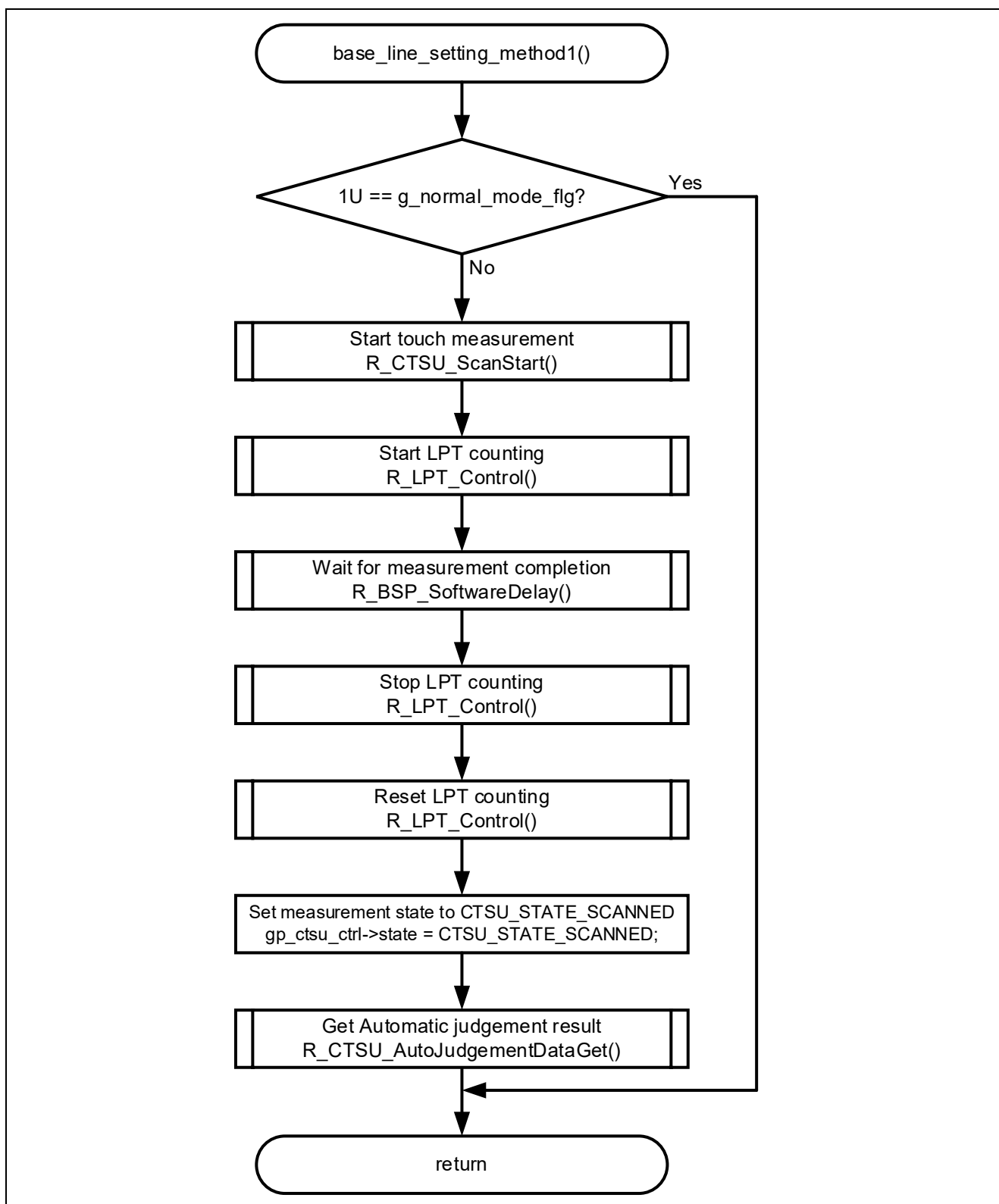


Figure 4-11 Flowchart of CTSU2SL baseline settings

4.2.9 Processing of software standby mode transition and CTSU2SL low power consumption measurement

The flowchart of software standby mode transition and CTSU2SL low power consumption measurement is shown below.

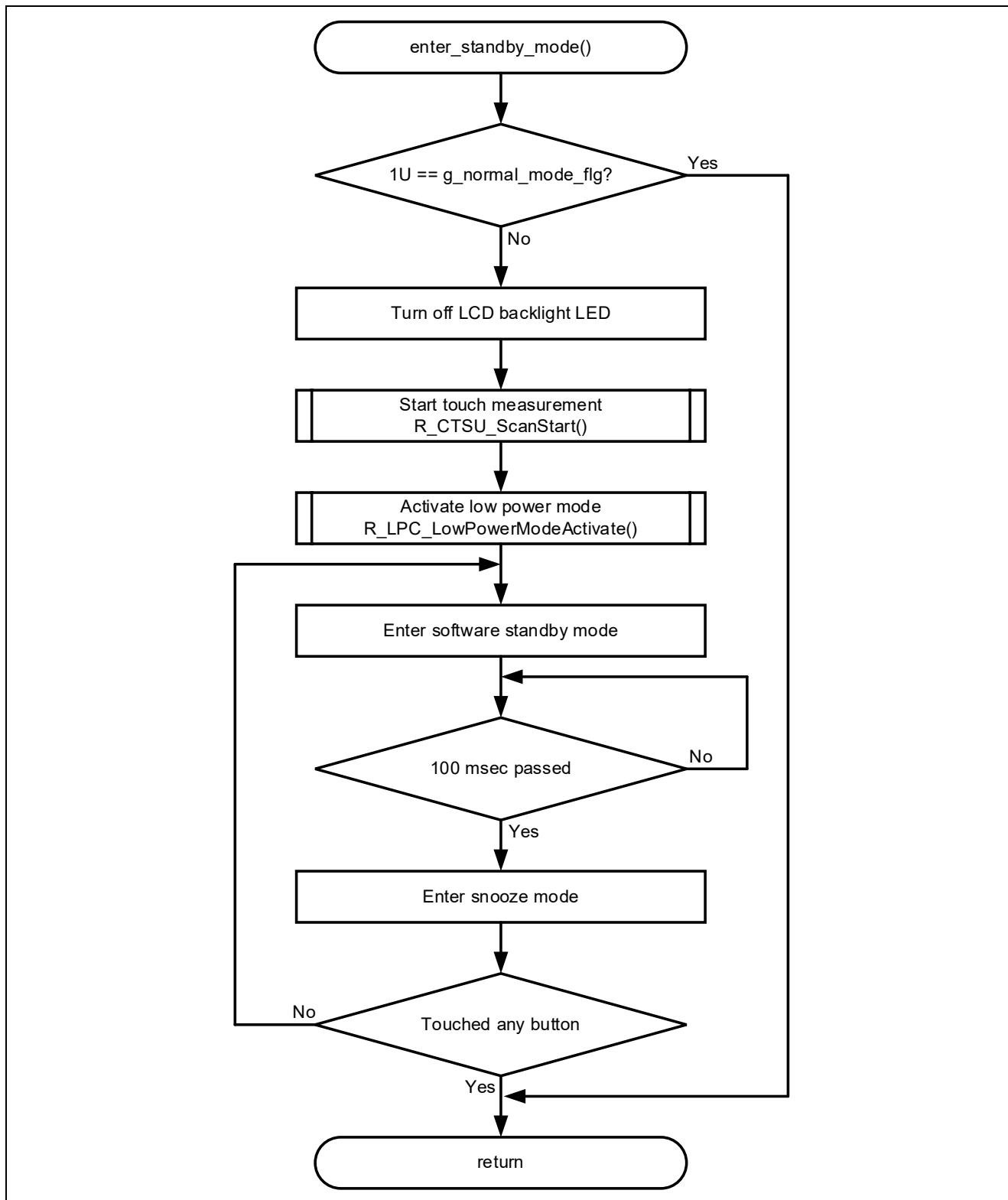


Figure 4-12 Flowchart of software standby mode transition and CTSU2SL low power consumption measurement

4.2.10 Processing of normal operation mode transition

The flowchart of normal operation mode transition is shown below.

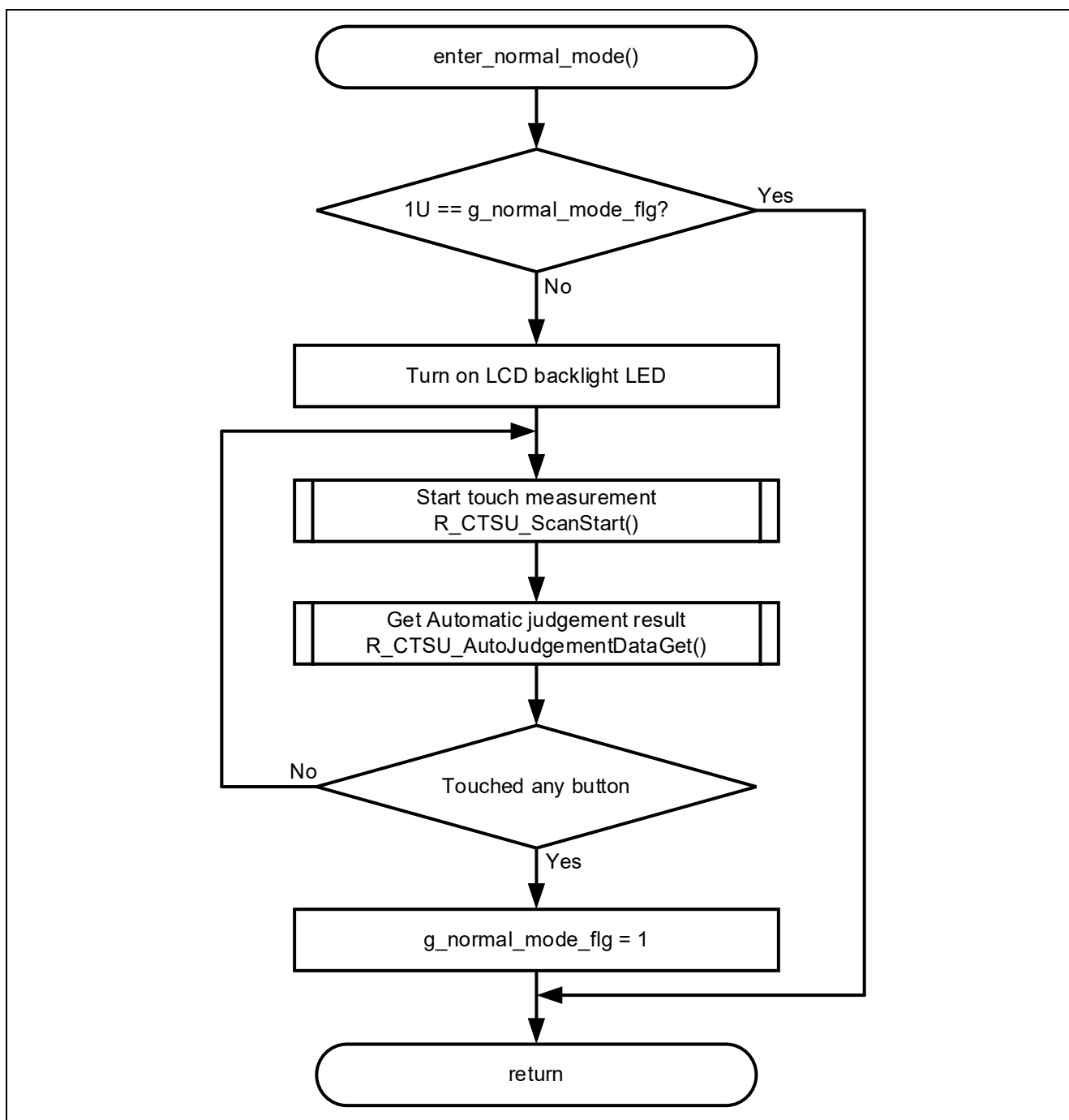


Figure 4-13 Flowchart of normal operation mode transition

4.2.11 Processing of CTSU2SL normal measurement

The flowchart of CTSU2SL normal measurement is shown below.

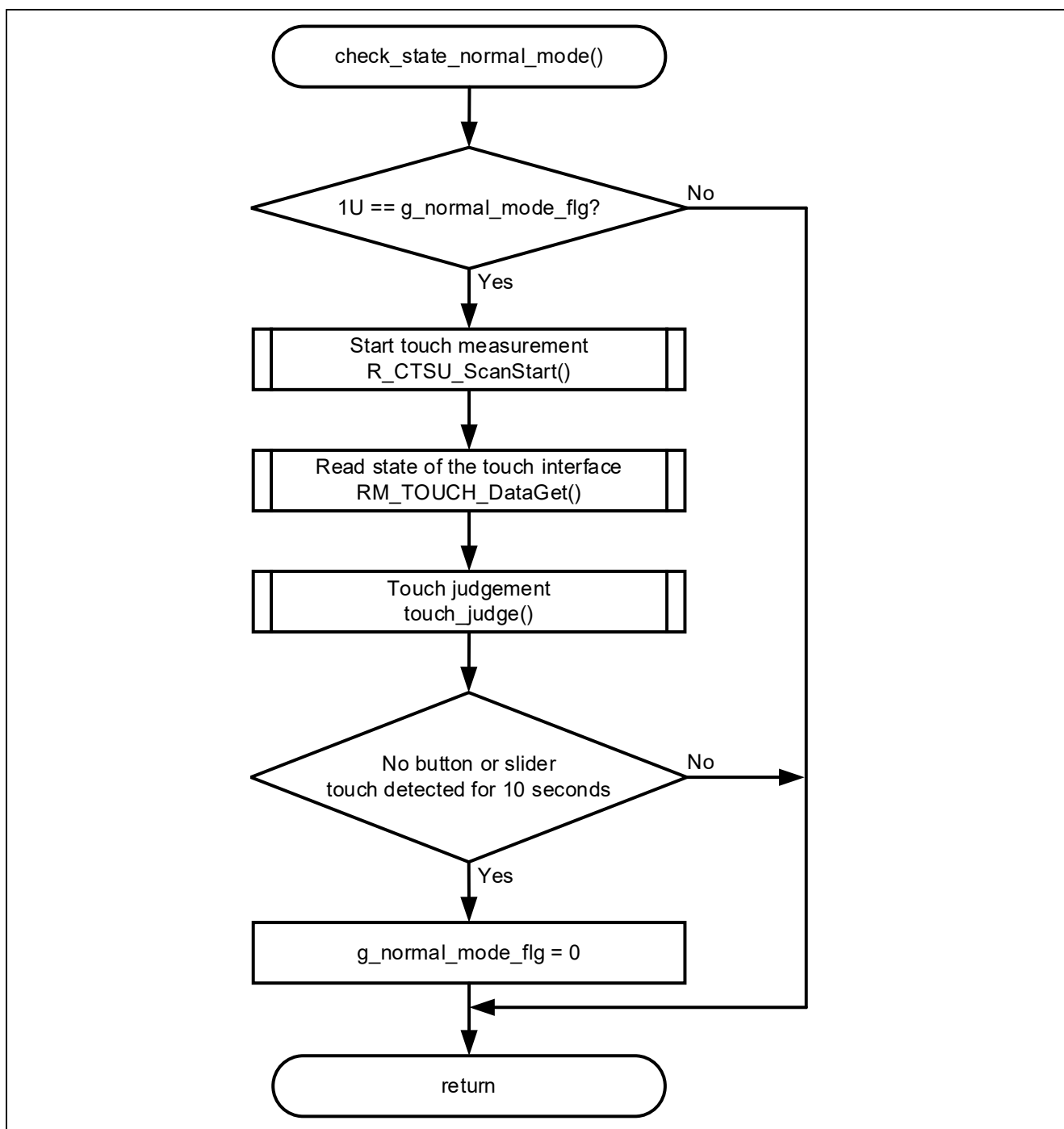


Figure 4-14 Flowchart of CTSU2SL normal measurement

4.2.12 Processing of touch judgement

The flowchart of touch judgement is shown below.

If the left side of the touch slider is touched after touching the right side of the touch slider, the touch slider is judged to have slid to the left. The same is true on the opposite side.

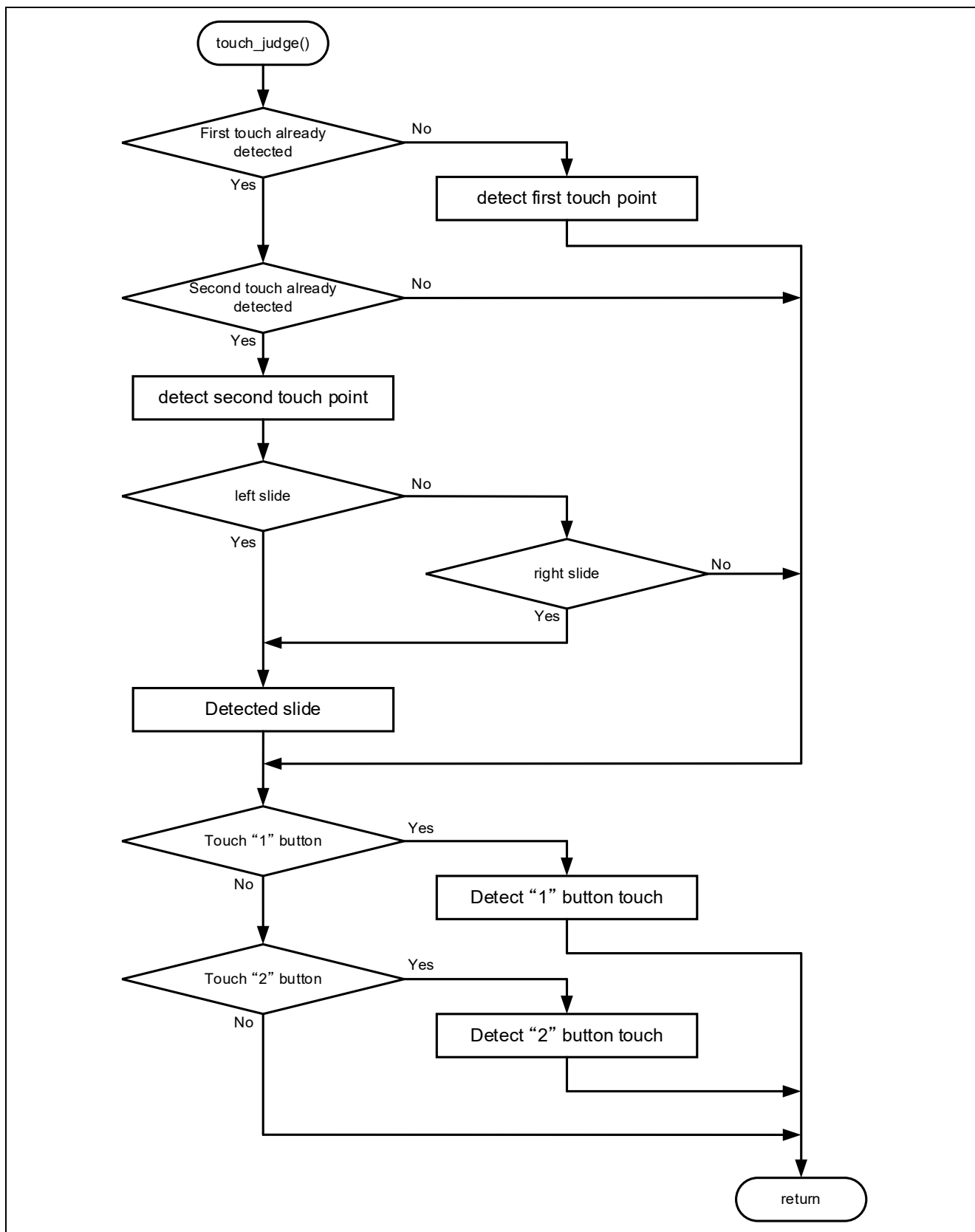


Figure 4-15 Flowchart of touch judgement

4.2.13 Processing of startup screen display

The flowchart of startup screen display is shown below.

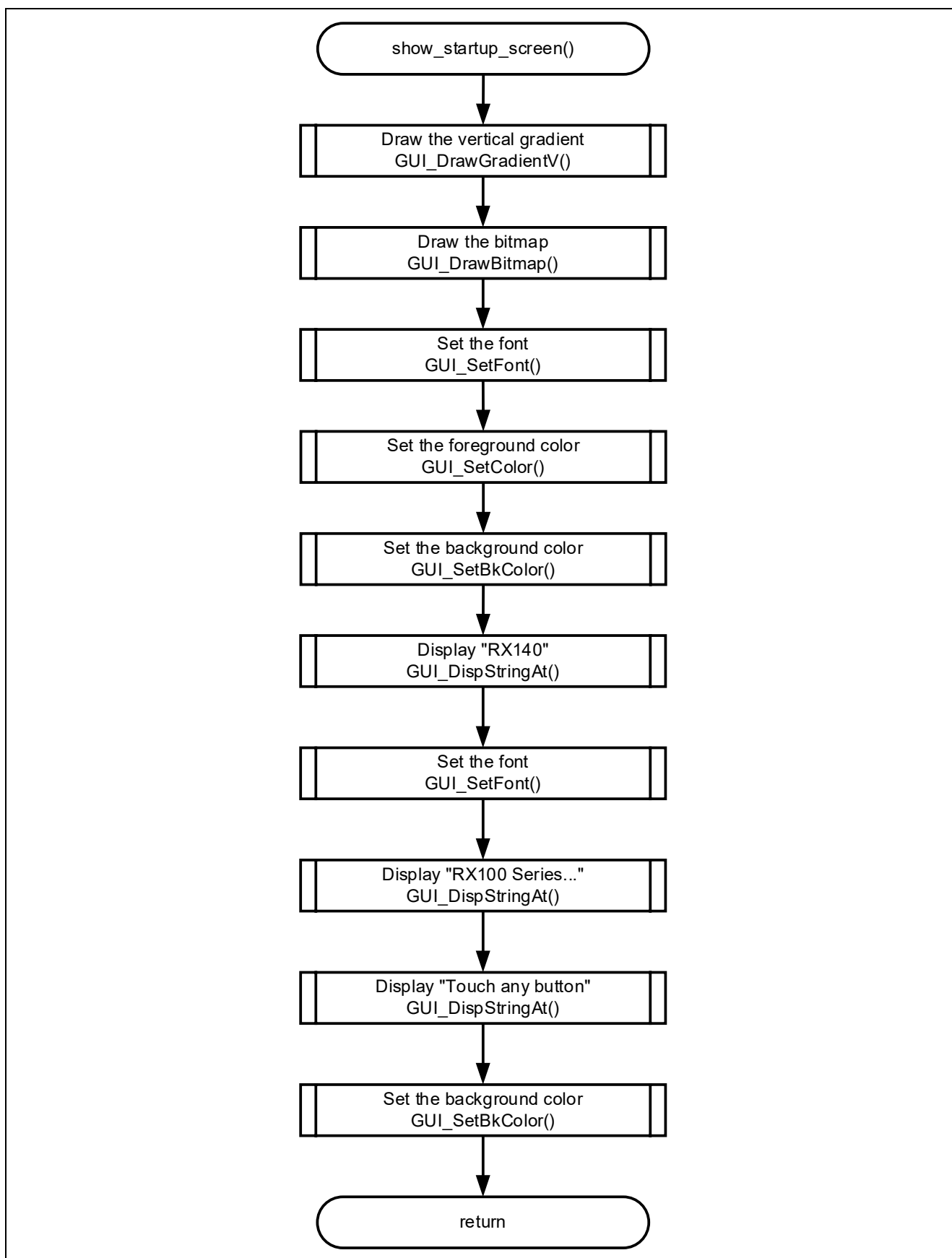


Figure 4-16 Flowchart of startup screen display

4.2.14 Processing of 5 seconds wait

The flowchart of 5 seconds wait is shown below.

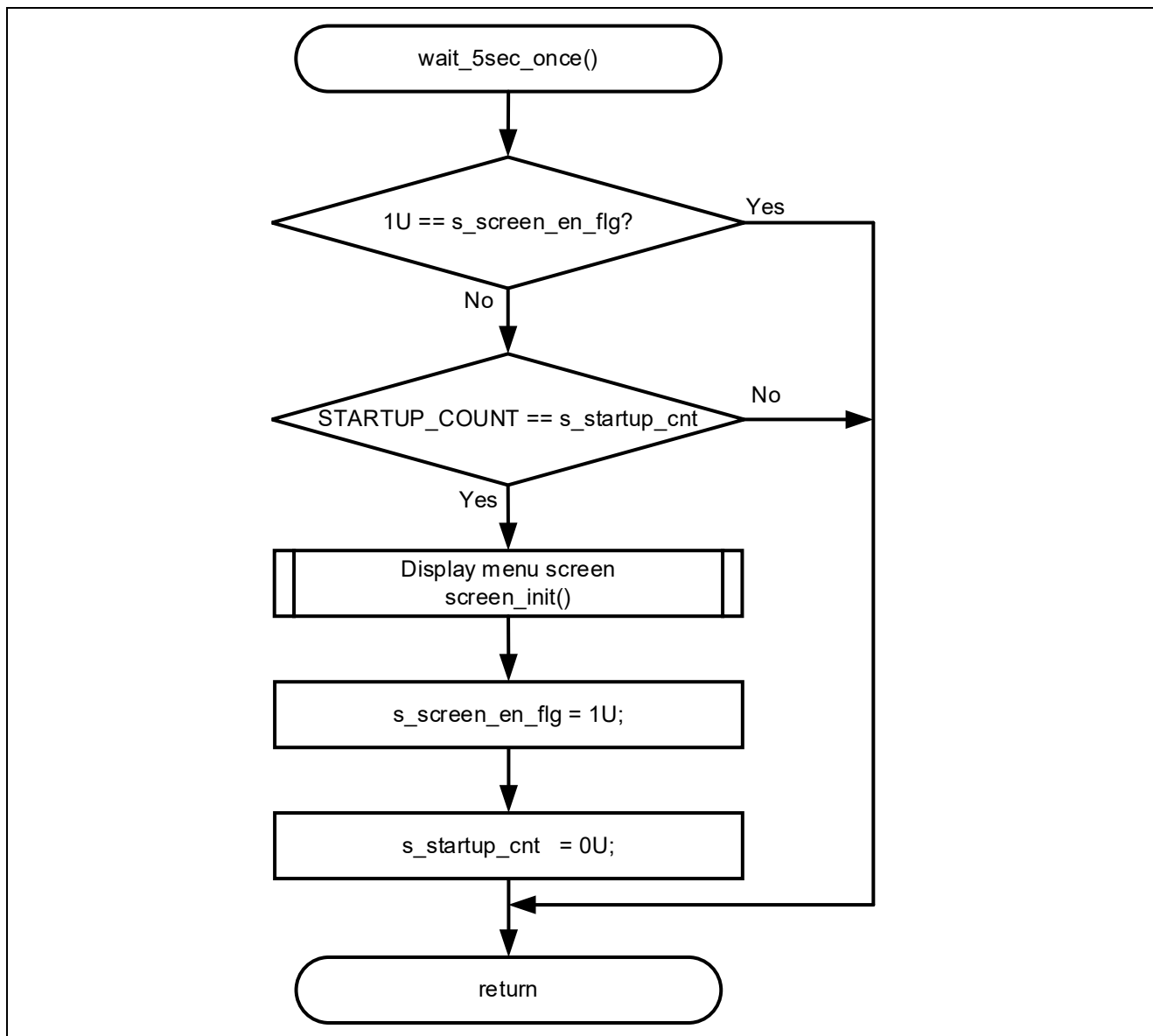


Figure 4-17 Flowchart of 5 seconds wait

4.2.15 Processing of screen initialization

The flowchart of screen initialization is shown below.

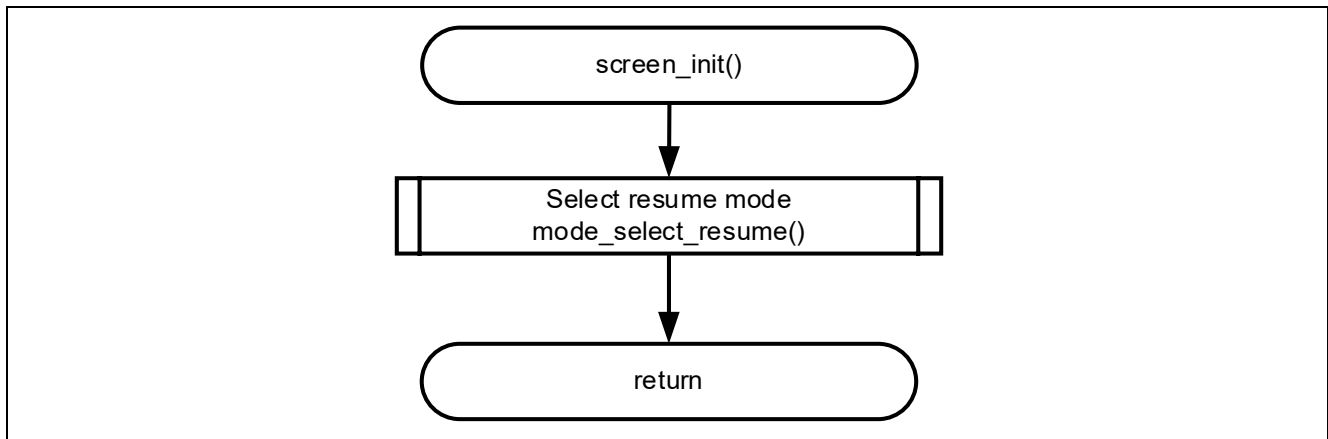


Figure 4-18 Flowchart of screen initialization

4.2.16 Processing of peripheral function initialization

The flowchart of peripheral function initialization is shown below.

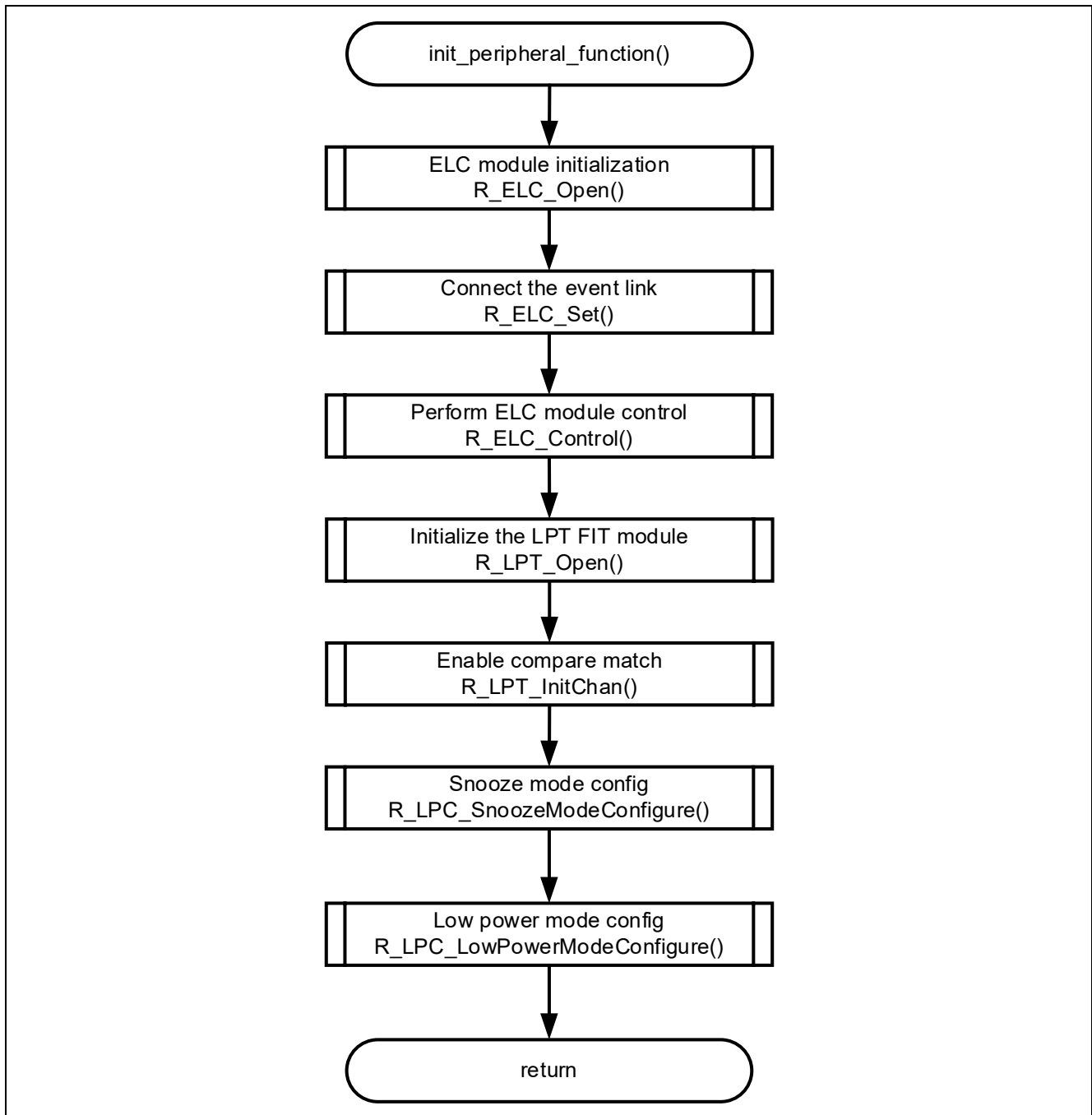


Figure 4-19 Flowchart of peripheral function initialization

4.2.17 Processing of offset initialization for tuning

The flowchart of offset initialization for tuning is shown below.

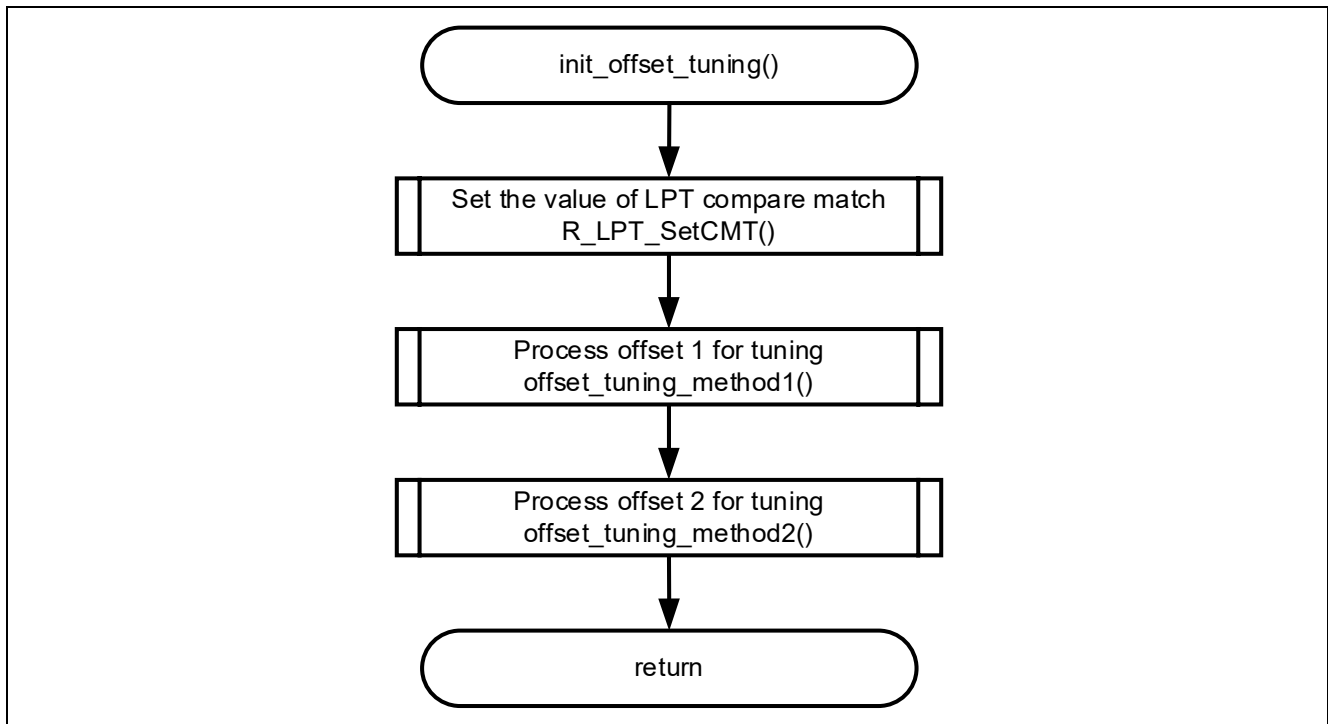


Figure 4-20 Flowchart of offset initialization for tuning

4.2.18 Processing of menu display resumption

The flowchart of menu display resumption is shown below.

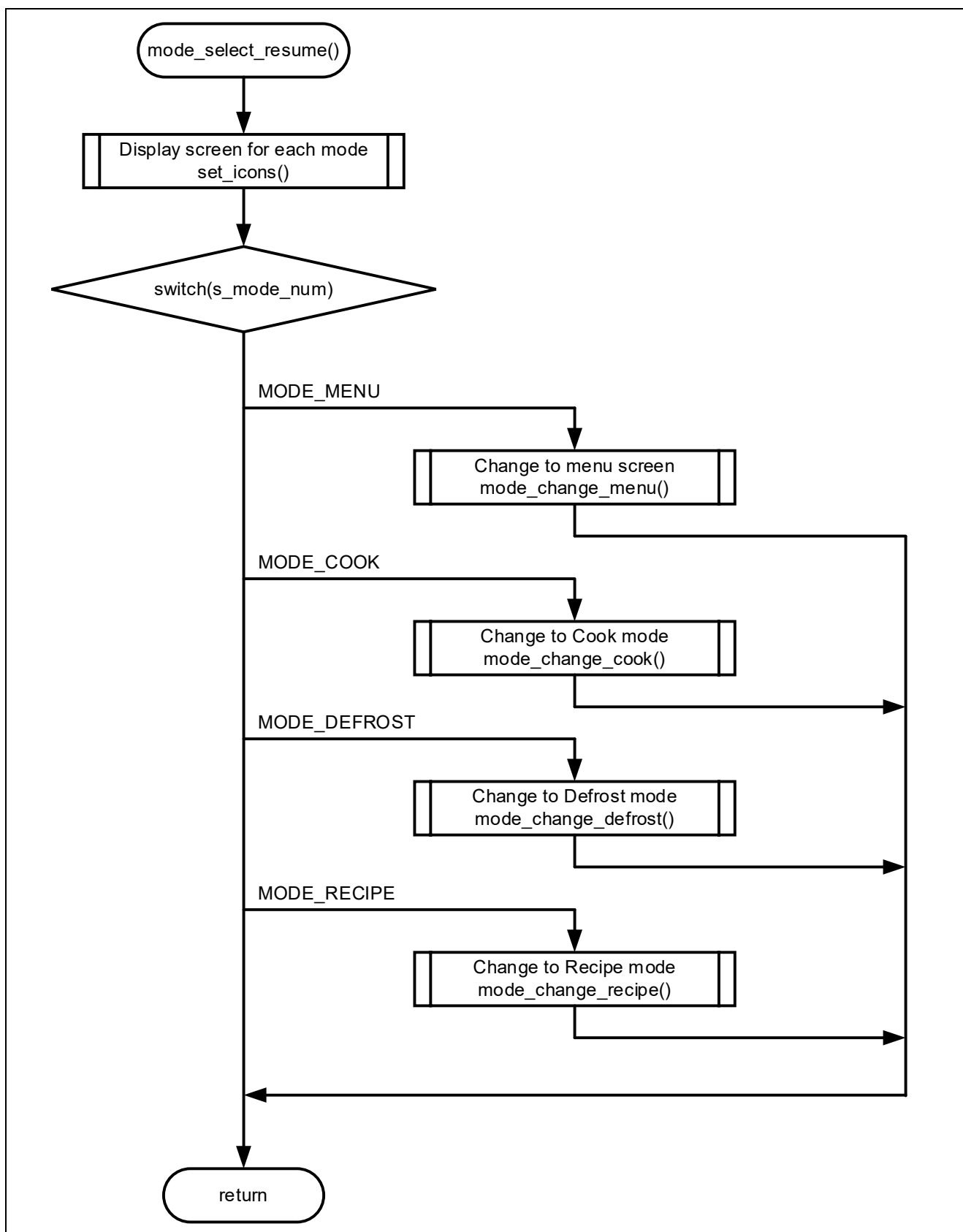


Figure 4-21 Flowchart of menu display resumption

4.3 Pins Used

The following shows lists pins used in this sample program.

Table 4-1 List of Pins and Functions

Pin Name	Input/Output	Function
PC5/RSPCKA	Input/Output	RSPI0 clock pin
P17/MISOA	Input	RSPI0 MISO pin
P16/MOSIA	Output	RSPI0 MOSI pin
PC4/TSCAP	-	TSCAP pin
PH3/TS7	Input	Electrostatic capacitance measurement pin
PH2/TS8	Input	Electrostatic capacitance measurement pin
PH1/TS9	Input	Electrostatic capacitance measurement pin
PH0/TS10	Input	Electrostatic capacitance measurement pin
P55/TS11	Input	Electrostatic capacitance measurement pin
P54/TS12	Input	Electrostatic capacitance measurement pin

4.4 Sample Program Structure

4.4.1 Peripheral Functions Used

The following shows lists peripheral functions used in this sample program.

Table 4-2 List of Peripheral Functions Used and Functions

Peripheral Functions	Function
RSPI0	SPI Communication with LCD
DTC	Used for measure CTSU2SL during snooze mode and RAM to RSPI transfer
ELC	Used for measure CTSU2SL during software standby mode
CTSU2SL	Used for with touch buttons and touch slider
CMT0	Used for internal emWin FIT
CMT2	Used for measure CTSU2SL during normal operation mode
LPT	Used for ELC triggering

4.4.2 Components Used

The following shows lists components used in this sample program.

Table 4-3 List of Components Used

Components	Abbreviation	Version
Board Support Package	r_bsp	7.21
Byte-based circular buffer library	r_byteq	2.10
CMT driver	r_cmt_rx	5.40
Control Low Power States	r_lpc_rx	2.10
CTSU QE API	r_ctsu_qe	2.20
DTC driver	r_dtc_rx	4.21
ELC Driver	r_elc_rx	2.01
GPIO Driver	r_gpio_rx	4.70
Graphic Library with Graphical User Interface	r_emwin_rx	6.32.a.1.00
Low-Power Timer Driver	r_lpt_rx	3.01
RSPI Driver	r_rspi_rx	3.04
Touch QE API	rm_touch_qe	2.20

4.4.3 Peripheral Function Settings

The Smart Configurator settings used in this sample program are shown below. The items and settings in each table in the Smart Configurator settings are described in the notation on the configuration screen.

Settings not listed are assumed to be default settings.

Table 4-4 Parameters of Smart Configurator (1/2)

Category	Item	Setting/Description
Smart Configurator >> Clock		The following settings are made on the "Clocks" Tab.
	VCC	5 (V)
	Main clock	Stopped: Unchecked.
	HOCO clock	Operation: Checked. HOCO oscillation enabled after reset
	LOCO clock	Stopped: Unchecked.
	IWDT dedicated clock	Operation: Checked. Frequency: 15 (kHz)
	System clock	Clock source: HOCO Flash IF clock (FCLK): 48MHz System clock (ICLK): 48MHz Peripheral module clock (PCLKB): 24MHz Peripheral module clock (PCLKD): 48MHz CLKOUT pin: Unchecked. Low power timer clock (LPTCLK) : 15kHz
Smart Configurator >> System		Debugging interfaces setting: FINE
Smart Configurator >> Components >> r_bsp		Other than the changes listed below, default settings are used.
	Heap size	0x4000
	Software Interrupt Unit1 (SWINT1)	Used
	Software Interrupt Task Buffer Number	8
	Initial value of the software interrupt priority	Priority level 1
Smart Configurator >> Components >> r_dtc_rx		Other than the changes listed below, default settings are used.
	DMAC FIT check	DMAC FIT modules is not used with DTC FIT module.
Smart Configurator >> Components >> r_elc_rx		Default settings are used.
Smart Configurator >> Components >> r_ctsu_qe		Other than the changes listed below, default settings are used.
	Data transfer of INTCTSUWR and INTCTSURD	DTC
	Select automatic judgement code	Enable
	TSCAP pin	Use: Checked.
	TS7 pin	Use: Checked.
	TS8 pin	Use: Checked.
	TS9 pin	Use: Checked.
	TS10 pin	Use: Checked.
	TS11 pin	Use: Checked.
	TS12 pin	Use: Checked.
Smart Configurator >> Components >> r_gpio_rx		Default settings are used.
Smart Configurator >> Components >> r_lpc_rx		Default settings are used.

Table 4-5 Parameters of Smart Configurator (2/2)

Category	Item	Setting/Description
Smart Configurator >> Components >> r_rspx_rx		Other than the changes listed below, default settings are used.
	Dummy data of reception	0x00
	RSPi0	Checked
	RSPCKA pin	Use: Checked.
	MOSIA pin	Use: Checked
	MISOA pin	Use: Checked
Smart Configurator >> Components >> r_cmt_rx		Default settings are used.
Smart Configurator >> Components >> r_lpt_rx		Other than the changes listed below, default settings are used.
	LPT clock source	IWDT-dedicated on-chip oscillator
Smart Configurator >> Components >> rm_touch_qe		Default settings are used.
Smart Configurator >> Components >> r_byteq		Default settings are used.
Smart Configurator >> Components >> r_emwin_rx		Other than the changes listed below, default settings are used.
	Configurations >> BasicSetting	
	Work area size for GUI	6000
	Horizontal LCD size	240
	Vertical LCD size	320
	Color depth	16 bit per pixel
	LCD orientation	ORIENTATION_CW
	Select DMA transfer modules	DTC
	Configurations >> Select LCD Interface	
	LCD interface	LCD_IF_RSPI
	Configurations >> Select LCD Interface >> SPI Interface Setting	
	LCD interface channel number	0
	Select LCD Driver IC	LCD_DRV_IC_ILI9341
	Communication baud rate of LCD interface	12000000
	Use or unused display cache	Unuse: Unchecked.
	Configurations >> Select LCD Interface >> LCD Interface Pin Setting	
	Use Display Signal Pin	Use Display Signal Pin
	Display Signal Pin	GPIO_PORT_C_PIN_6
	Use Backlight Pin	Use Backlight Pin
	Backlight Pin	GPIO_PORT_C_PIN_7
	Use Data/Command Pin	Use Data/Command Pin
	Data/Command Pin	GPIO_PORT_E_PIN_4
	Use Chip Select Pin	Use Chip Select Pin
	Chip Select Pin	GPIO_PORT_B_PIN_2
	Configurations >> Select Touch Interface	
	Use Touch function	Not use Touch function: Unchecked.

4.4.4 File Structure

The following shows file structure by sample program.

Table 4-6 File Structure

Folder name, File name	Outline
src	Folder for program source
└ main.c	Source file for main processing
└ main.h	Header file for main processing
└ LCD_custom_func.c	Source file for LCD related
└ LCD_custom_func.h	Header file for LCD related
└ r_low_power_control.c	Source file for operation mode control related
└ r_low_power_control.h	Header file for operation mode control related
└ touch_func.c	Source file for touch related
└ touch_func.h	Header file for touch related
└ Resource	Folder for image and font
└ smc_gen	Smart Configurator generation
└└ r_byteq	
└└ r_cmt_rx	
└└ r_ctsu_qe	
└└ r_dtc_rx	
└└ r_elc_rx	
└└ r_emwin_rx	
└└ r_gpio_rx	
└└ r_lpc_rx	
└└ r_lpt_rx	
└└ r_rspi_rx	
└└ rm_touch_qe	
└└ general	
└└ r_bsp	
└└ r_config	
└└└ r_pincfg	
qe_gen	
QE-Touch	
	QE-Touch generation

4.4.5 Variables

The following shows the variables that are used in this sample program.

Table 4-7 List of variables used in the sample code

Variable name	Type	Contents
g_normal_mode_flg	uint8_t	The Normal operation mode flag
g_touch_timer_flg	uint8_t	The touch judgement start flag in normal operation mode
g_lcd_left_slide_flg	uint8_t	The touch slider slid to the left flag
g_lcd_right_slide_flg	uint8_t	The touch slider slid to the right flag
g_lcd_push_back_flg	uint8_t	The "1" button was touched flag
g_lcd_push_enter_flg	uint8_t	The "2" button was touched flag
g_lcd_push_hold_flg	uint8_t	Flag indicating that the touch button is touched
s_flg_touch	uint8_t	Touch buttons status
s_mode_num	uint8_t	Mode status
s_setting_target	uint8_t	Flags indicating screen status
s_screen_en_flg	uint8_t	Flag indicating initial screen status
s_startup_cnt	uint8_t	Counter for initial screen display time management

4.4.6 Constants

The following shows the constants that are used in this sample program.

Table 4-8 List of constants used in the sample code

Constant Name	Setting Value	Contents
TOUCH_NO	(0U)	Value at no-operation
TOUCH_LEFT_SLIDE	(4U)	Value indicating that touch slider is slid to the left
TOUCH_RIGHT_SLIDE	(3U)	Value indicating that touch slider is slid to the right
TOUCH_ENTER	(1U)	Value indicating that "2" button was touched
TOUCH_BACK	(2U)	Value at moving to the previous screen
MODE_MENU	(0U)	Value of mode not selected
MODE_RECIPE_DETAIL	(6U)	Value of detail setting in Recipe mode
MODE_COOK_DETAIL	(3U)	Value of detail setting in Cook mode
MODE_DEFROST_DETAIL	(4U)	Value of detail setting in Defrost mode
MODE_COOK	(1U)	Value of start cooking in Cook mode
MODE_DEFROST	(2U)	Value of start cooking in Defrost mode
MODE_RECIPE	(5U)	Value of start cooking in Recipe mode
TOUCH_START	(5U)	Value of execution in each mode
SETTING_TOP	(0U)	Value of initial screen
STARTUP_COUNT	(STARTUP_TIME * CMT_FREQ)	Initial screen display time (Count)

4.4.7 Functions

The following shows the functions that are used in this sample program.

Table 4-9 List of functions used in the sample code

Function name	Outline
main	Main process
init_low_power_control	CTSU2SL for low-power measurement initial settings
GUI_Init	Initializing emWin
show_startup_screen	Processing of startup screen display
wait_5sec_once	Processing of 5 seconds wait
base_line_setting_method1	CTSU2SL baseline settings
enter_standby_mode	Software standby mode transition
enter_normal_mode	Normal operation mode transition
check_state_normal_mode	Touch judgement in normal operation mode
screen_init	Processing of screen initialization
change_screen	LCD screen update
init_peripheral_function	Processing of peripheral function initialization
init_offset_tuning	Processing of offset initialization for tuning
touch_judge	Touch judgement
mode_select_resume	Processing of menu display resumption
slide_func	Processing at touch slider operation
enter_pushed_func	Processing when "2" button is touched
back_pushed_func	Processing when "1" button is touched
start_pushed_func	Processing when "2" button is touched
offset_tuning_method1	Processing of offset 1 for tuning
offset_tuning_method2	Processing of offset 2 for tuning
set_icons	Processing of screen display for each mode
mode_change_menu	Move to the menu screen
mode_change_cook	Move to Cook mode
mode_change_defrost	Move to Defrost mode
mode_change_recipe	Move to Recipe mode
slide_icons	Processing of cursor movement on menu screens and mode selection screens for Cook, Defrost and Recipe
setting_cook	Setting the number of watts and seconds in Cook mode
setting_defrost	Setting the level of defrosting and the number of grams in Defrost mode
setting_recipe	Setting the number of cupcakes in Recipe mode
mode_select_enter	Change the mode and display the LCD screen according to the mode
change_target_cook	Change the setting target of the detail setting screen in Cook mode
change_target_defrost	Change the setting target of the detail setting screen in Defrost mode
start_cook	Start cooking in Cook mode
start_defrost	Start defrosting in Defrost mode
start_recipe	Start cooking in Recipe mode
start_cook_detail	Start of detail setting in Cook mode
start_defrost_detail	Start of detail setting in Defrost mode
start_recipe_detail	Start of detail setting in Recipe mode

4.4.8 Function Specifications

The following shows function specifications that are used in this sample program.

[Function name] main

Outline	Main process
Header	None
Declaration	void main (void)
Description	Initializes peripheral functions and controls touch keys and LCD.
Arguments	None
Return value	None
Remarks	None

[Function name] init_low_power_control

Outline	CTS2SL for low-power measurement initial settings
Header	r_low_power_control.h
Declaration	void init_low_power_control (void)
Description	CTS2SL for low-power measurement initial settings.

Arguments	None
Return value	None
Remarks	None

[Function name] GUI_Init

Outline	Initializing emWin
Header	GUI.h
Declaration	void GUI_Init (void)
Description	Initializes emWin internal data structures and variables.
Arguments	None
Return value	None
Remarks	None

[Function name] show_startup_screen

Outline	Processing of startup screen display
Header	R_low_power_control.h
Declaration	void show_startup_screen (void)
Description	Performs startup screen display.
Arguments	None
Return value	None
Remarks	None

[Function name] base_line_setting_method1

Outline	CTS2SL baseline settings
Header	r_low_power_control.h
Declaration	void base_line_setting_method1 (void)
Description	CTS2SL baseline settings.
Arguments	None
Return value	None
Remarks	None

[Function name] enter_standby_mode

Outline	Software standby mode transition
Header	r_low_power_control.h
Declaration	void enter_standby_mode (void)
Description	Turn off LCD panel backlight and transition to software standby mode.
Arguments	None
Return value	None
Remarks	None

[Function name] enter_normal_mode

Outline	Normal operation mode transition
Header	r_low_power_control.h
Declaration	void enter_normal_mode (void)
Description	Turn on LCD panel backlight and transition to normal operation mode.
Arguments	None
Return value	None
Remarks	None

[Function name] check_state_normal_mode

Outline	Touch judgement in normal operation mode
Header	r_low_power_control.h
Declaration	void check_state_normal_mode (void)
Description	Performs touch judgement in normal operation mode.
Arguments	None
Return value	None
Remarks	None

[Function name] screen_init

Outline	Processing of screen initialization
Header	LCD_custom_func.h
Declaration	void screen_init (void)
Description	Performs screen initialization.
Arguments	None
Return value	None
Remarks	None

[Function name] change_screen

Outline	LCD screen update
Header	LCD_custom_func.h
Declaration	void change_screen (void)
Description	Updates the LCD screen by touch operation.
Arguments	None
Return value	None
Remarks	None

[Function name] touch_judge

Outline	Touch judgement
Header	touch_func.h
Declaration	void touch_judge (uint64_t button_status, uint16_t slider_position)
Description	Performs touch judgement and sets the judgement result to a flag.
Arguments	button_status, slider_position
Return value	None
Remarks	None

4.4.9 ROM/RAM usage

ROM/RAM usage for this sample program is shown below.

Table 4-10 ROM usage

Size (KByte)	description
63	LCD Graphic data
110	emWin, LCD control
16	Touch (sleep)
17	demo program
28	other
Total 234KByte	MAX 256Kbyte (91.4% Used)

Table 4-11 RAM usage

Size (KByte)	description
25	bitmap work area
16	heap area
6	emWin work area
8	other
Total 55KByte	MAX 64KByte (86% Used)

5. Importing a Project

The sample program is distributed in e² studio project format. This section shows how to import a project into e² studio or CS+. After importing a project, check the build and debug settings.

5.1 Procedure in e² studio

To use sample programs in e² studio, follow the steps below to import them into e² studio. In projects managed by e² studio, do not use space codes, multibyte characters, and symbols such as "\$", "#", "%" in folder names or paths to them.

(Note that depending on the version of e² studio you are using, the interface may appear somewhat different from the screenshots below.)

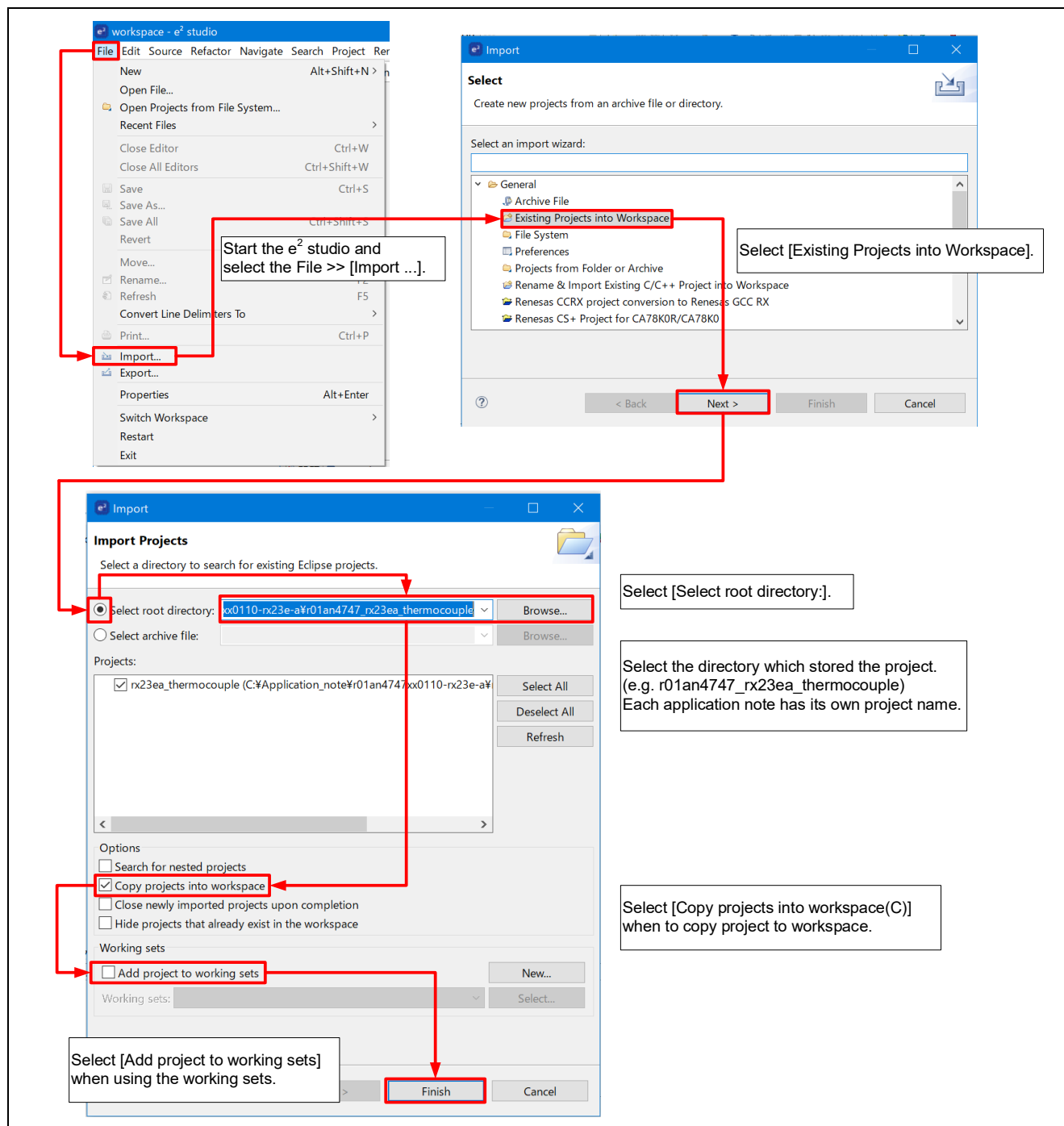


Figure 5-1 Import a Project into e² Studio

5.2 Procedure in CS+

To use sample programs in CS+, follow the steps below to import them into CS+. In projects managed by CS+, do not use space codes, multibyte characters, and symbols such as "\$", "#", "%" in folder names or paths to them.

(Note that depending on the version of CS+ you are using, the interface may appear somewhat different from the screenshots below.)

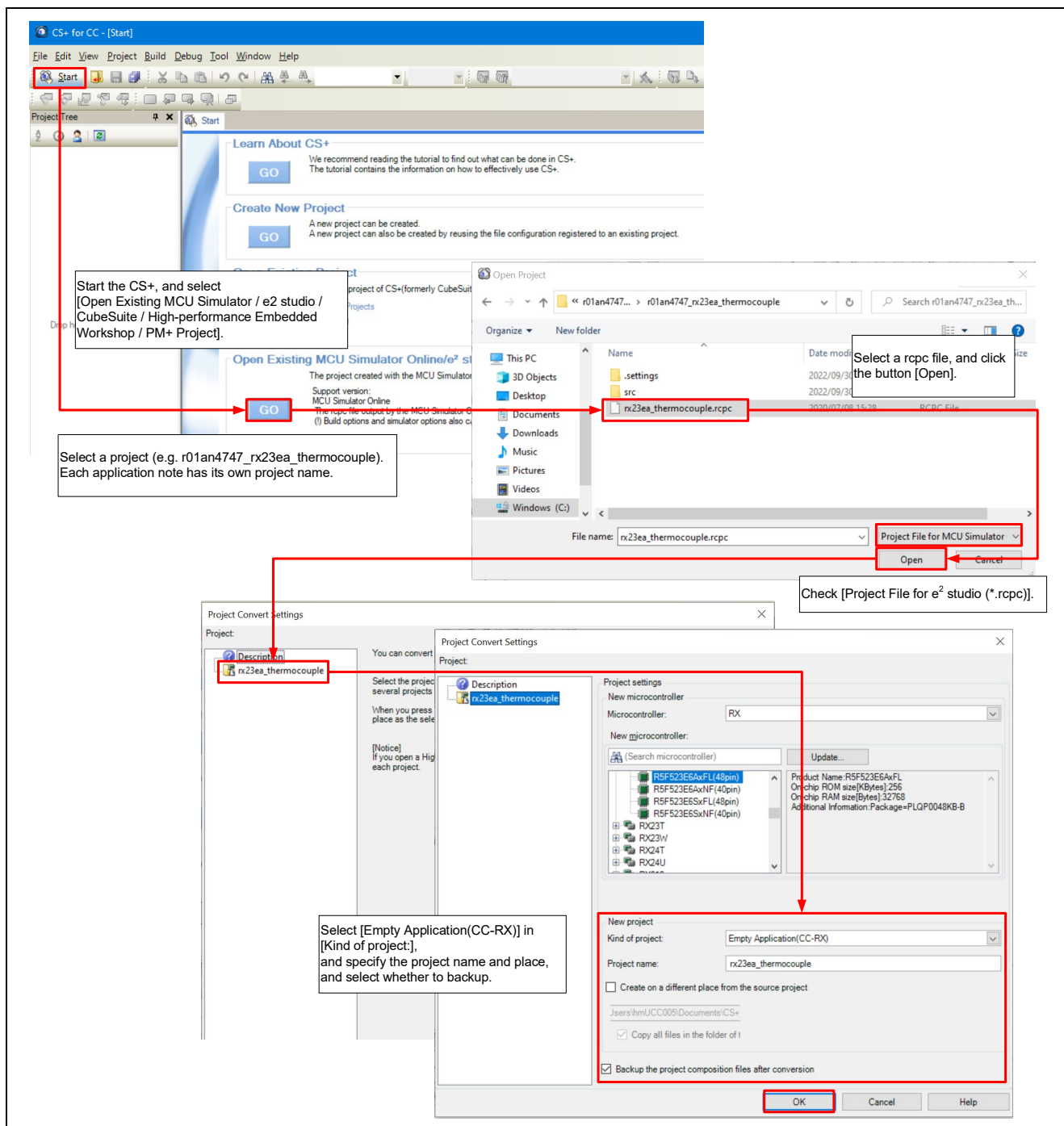


Figure 5-2 Import a Project into CS+

6. Start Demonstration

Disconnect the E2 Emulator Lite and turn on Renesas Starter Kit for RX140 to start the demonstration program. This demonstration program assumes control of the display and settings of a microwave oven. Set the cooking conditions and recipe selections using the touch buttons and touch slider while checking the LCD.

Hereinafter, touch buttons are described as buttons and touch slider is described as slider.

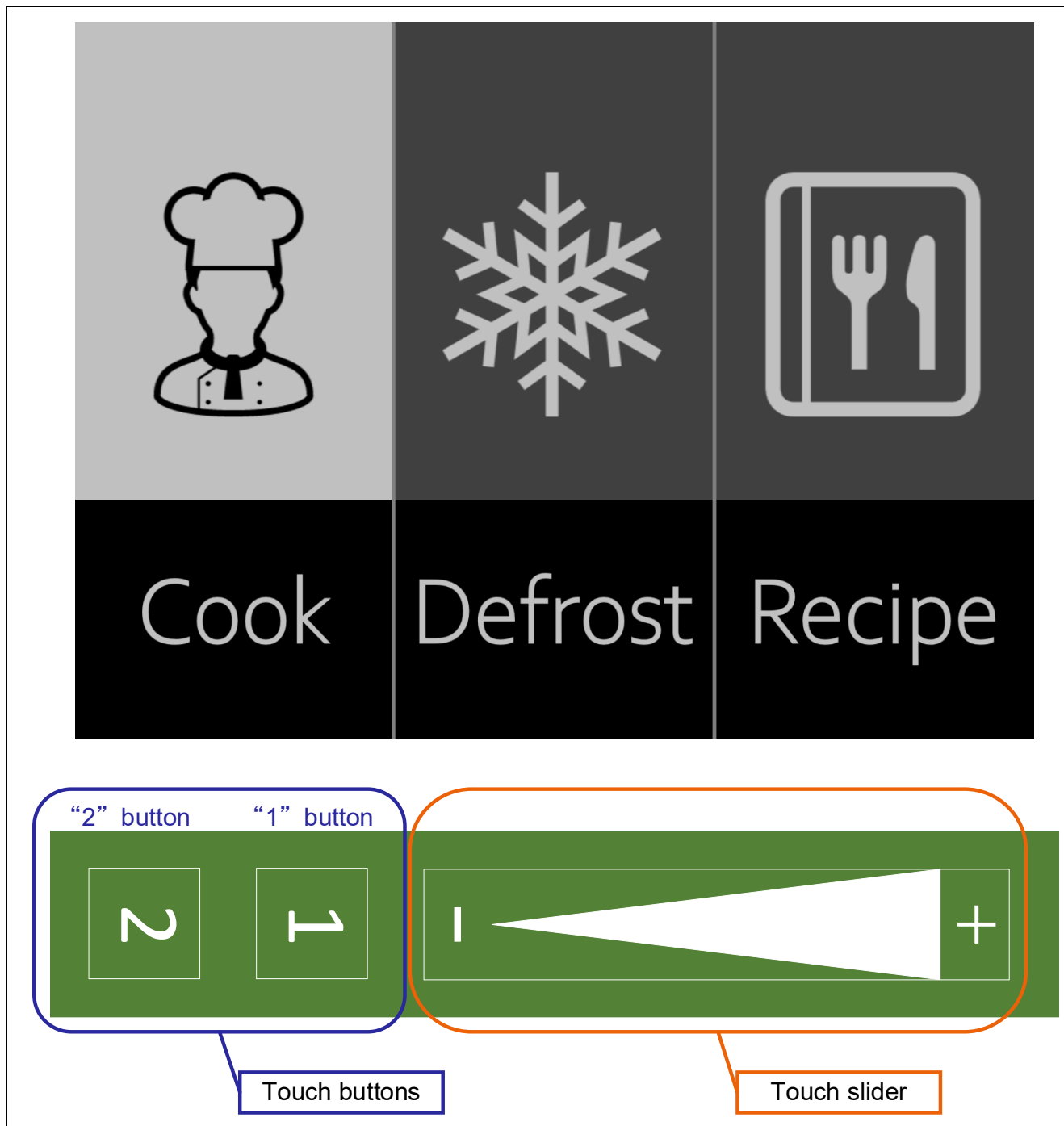


Figure 6-1 Demonstration screen and operation panel

6.1 Powered on Renesas Starter Kit for RX140 and menu screen

When Renesas Starter Kit for RX140 is powered on, the LCD panel displays the RX logo and RX140 features (initial screen) for approximately 5 seconds. When the display finishes, the sample program starts and becomes a menu screen.

And while the initial screen is displayed, can immediately move to the menu screen by touching one of the buttons.

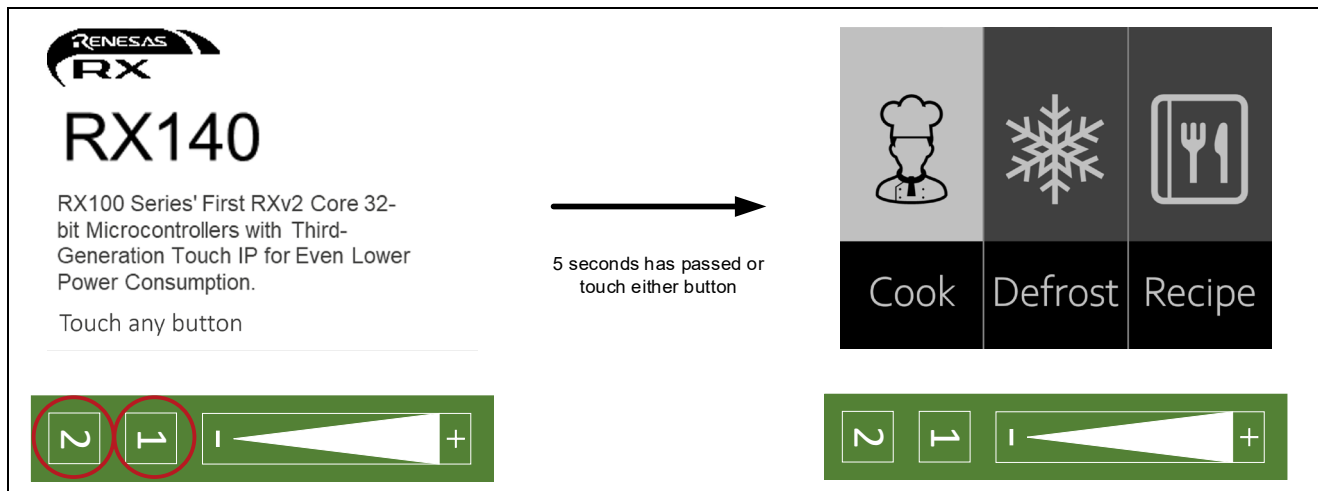


Figure 6-2 Start of the demonstration

6.2 Menu screen

"Cook", "Defrost" or "Recipe" can be selected with the slider operation on the menu screen.

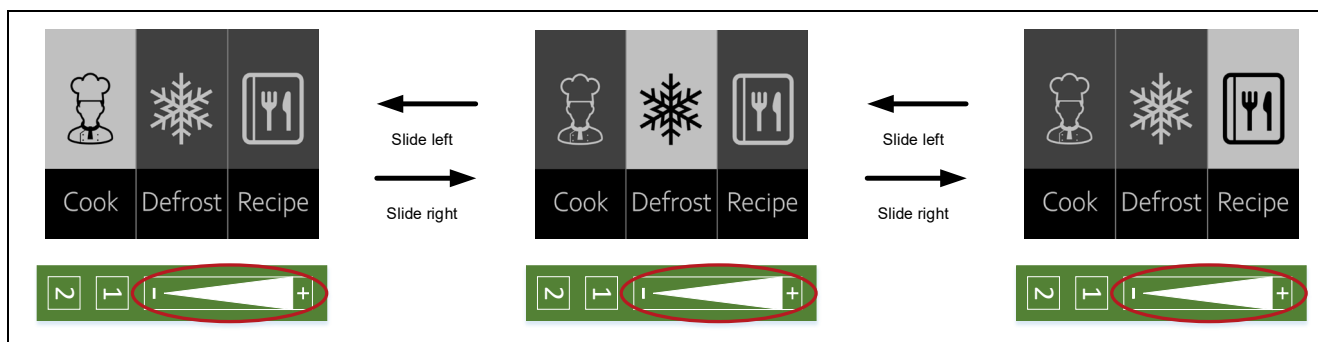


Figure 6-3 How to operate the menu screen

6.3 Cook setting

6.3.1 Move to mode selection screen

While "Cook" is selected on the menu screen, touching the "2" button can move to the Cook mode selection screen.

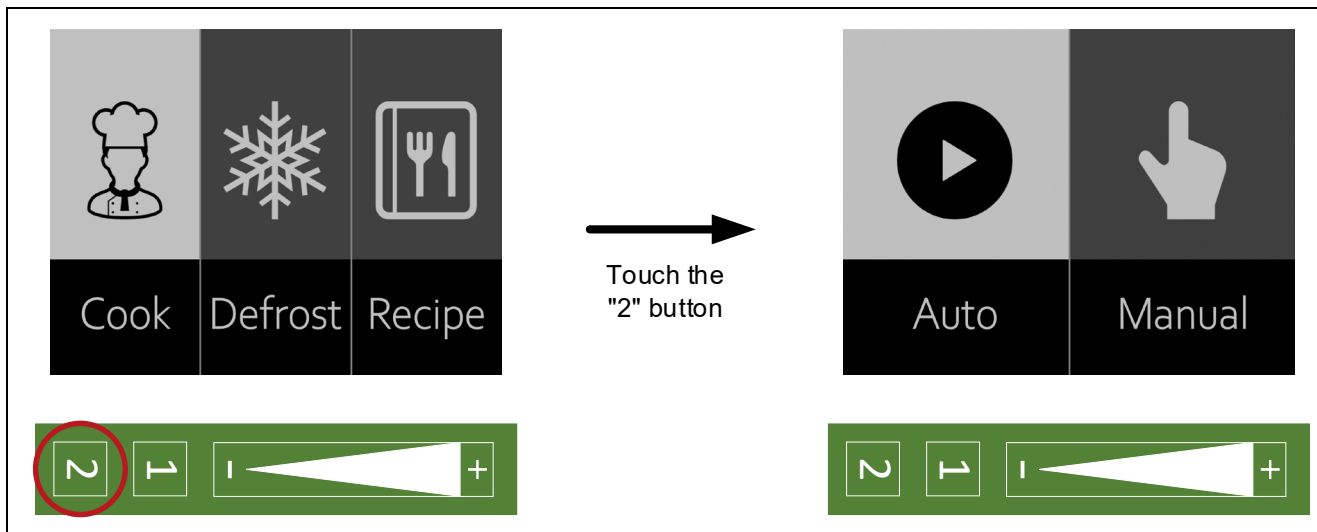


Figure 6-4 Move to the Cook mode selection screen

6.3.2 Select mode

While the Cook mode selection screen is displayed, "Auto" or "Manual" can be selected with the slider operation.

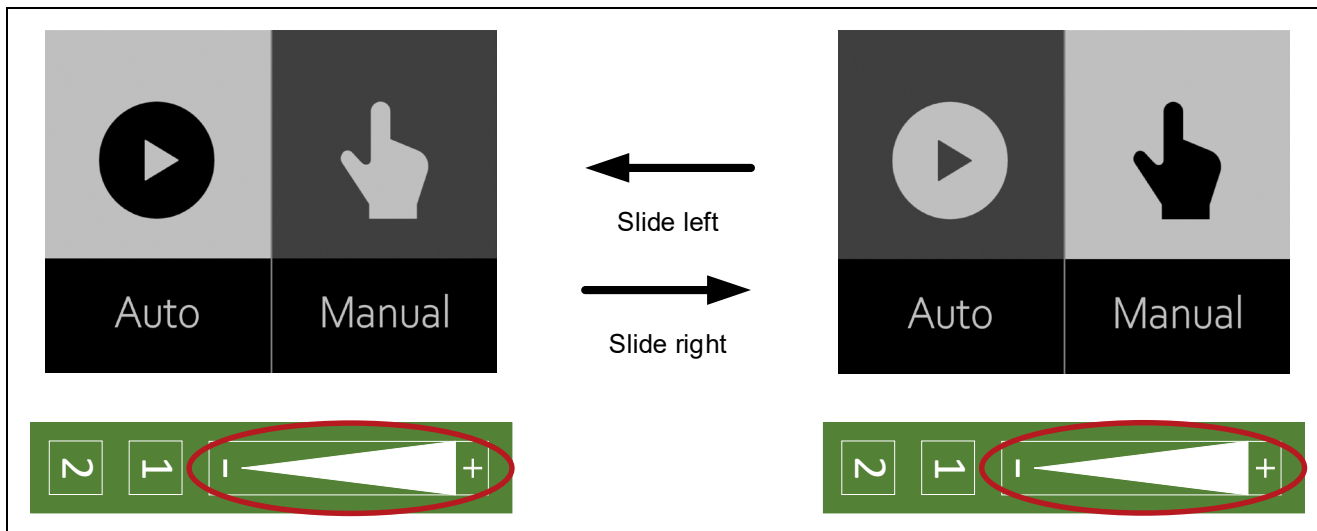


Figure 6-5 How to operate the Cook mode selection screen

6.3.3 Select Auto

While "Auto" is selected on the Cook mode selection screen, touching the "2" button can start cooking.

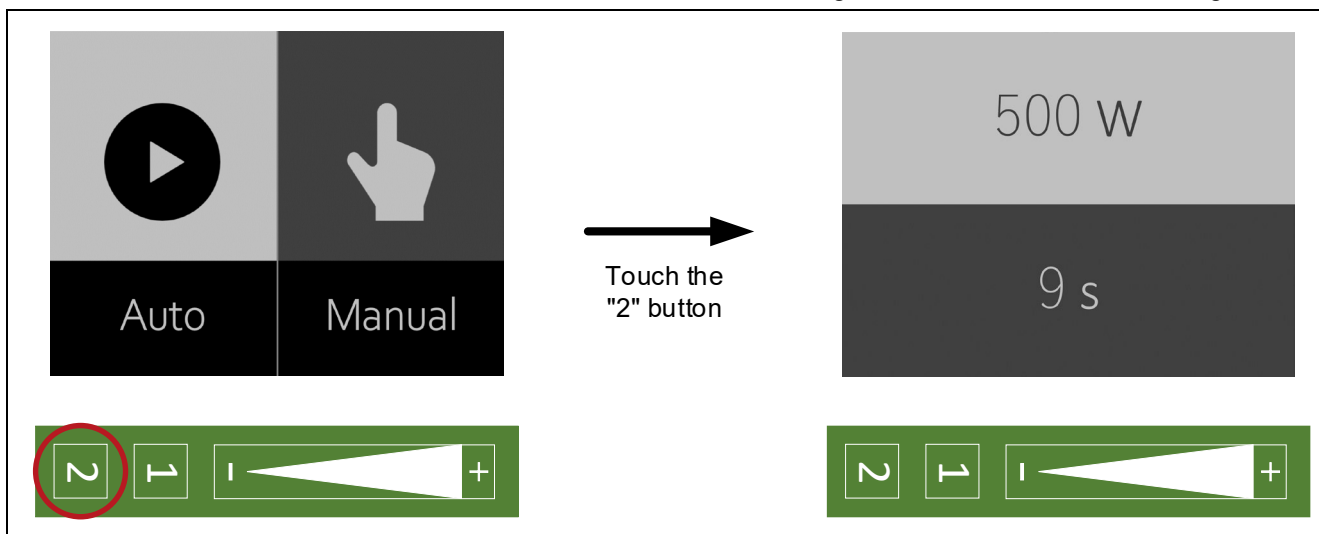


Figure 6-6 Start cooking in Auto mode

6.3.4 Select Manual

While "Manual" is selected on the Cook mode selection screen, touching the "2" button can move to the Cook detail setting screen.

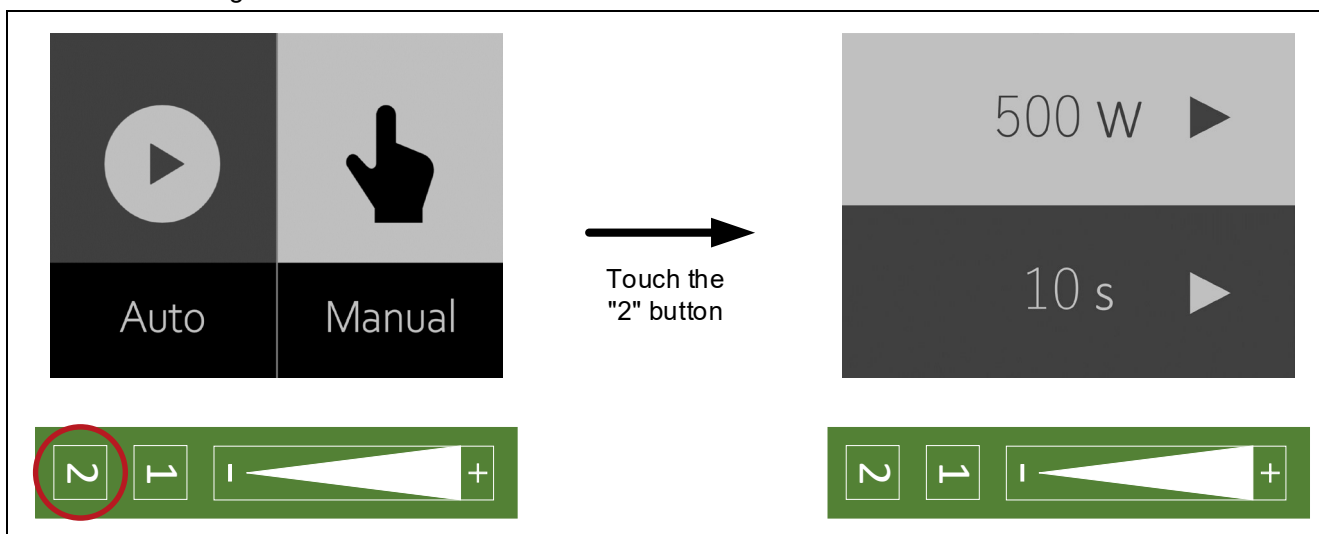


Figure 6-7 Move to the Cook detail setting screen

6.3.4.1 Set the number of watts

While the cursor is on the upper side, the number of watts can be set with the slider. "500W", "600W" and "700W" can be selected as the power level.

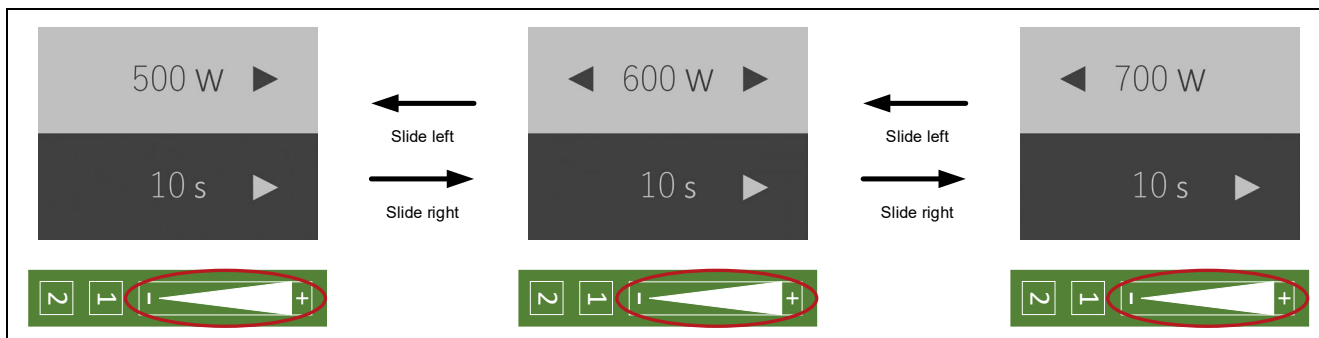


Figure 6-8 Setting the number of watts

6.3.4.2 Move the cursor

While the Cook detail setting screen is displayed, touching the "2" button can move the cursor. The item with a light-colored background is selected.

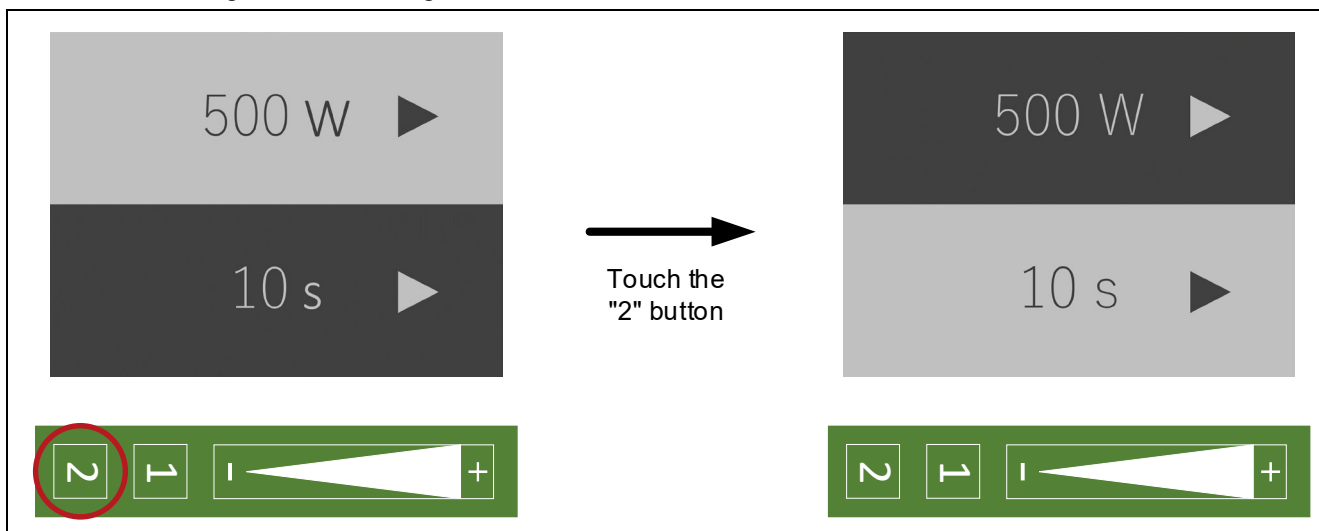


Figure 6-9 How to operate the cursor on the Cook detail setting screen

6.3.4.3 Set the number of seconds

While the cursor is on the lower side, the number of seconds can be set with the slider. "10s", "20s" and "30s", can be selected as the cooking time.

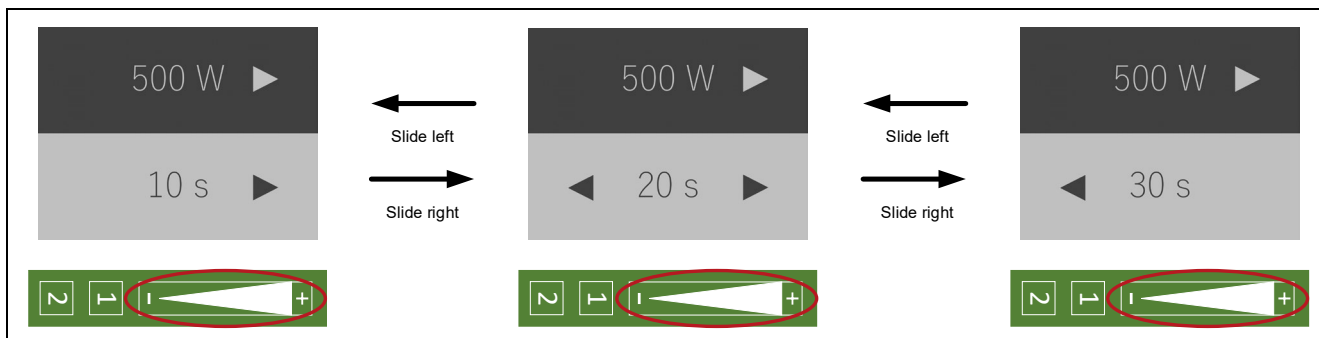


Figure 6-10 Setting the number of seconds

6.3.4.4 Start cooking

While the Cook detail setting screen is displayed and the cursor is on the lower side, touching the "2" button can start cooking.

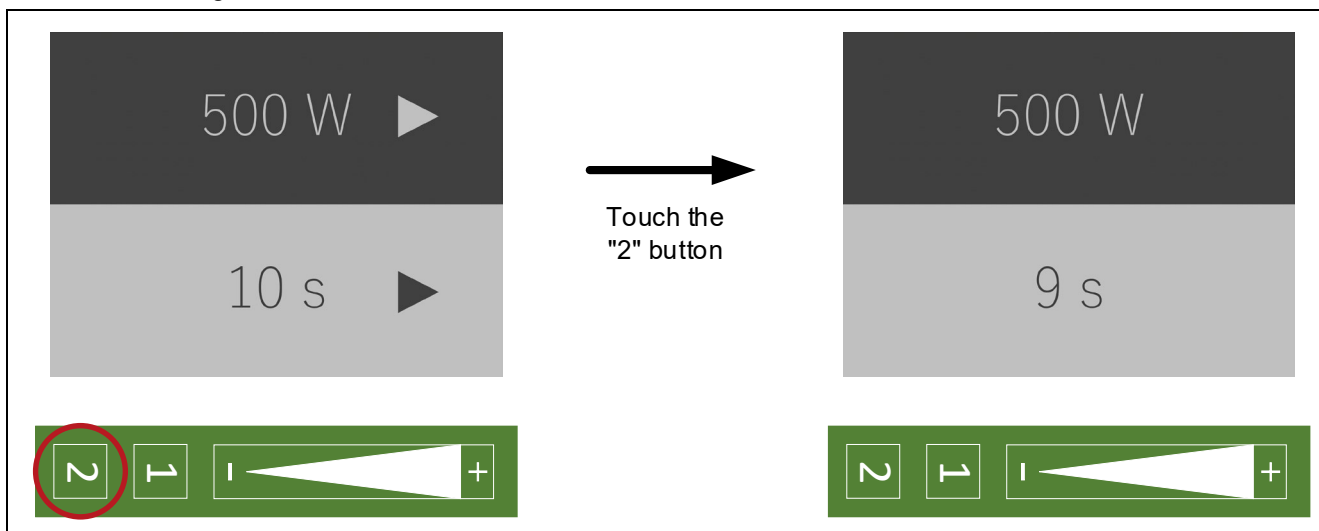


Figure 6-11 Start cooking in Manual mode

6.4 Defrost setting

6.4.1 Move to mode selection screen

While "Defrost" is selected on the menu screen, touching the "2" button can move to the Defrost mode selection screen.

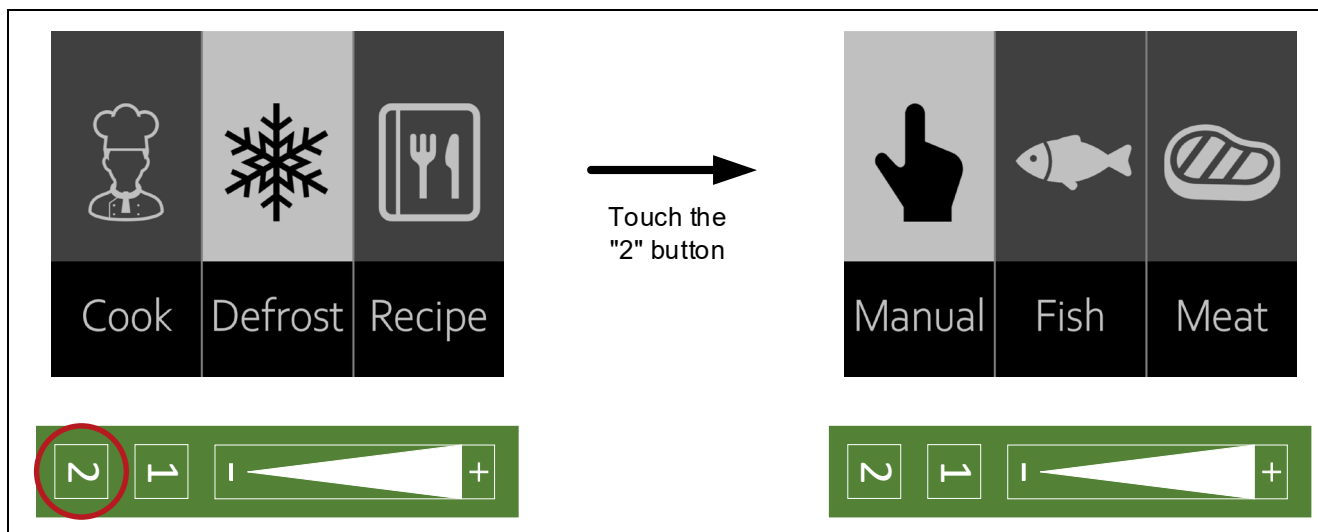


Figure 6-12 Move to the Defrost mode selection screen

6.4.2 Select mode

While the Defrost mode selection screen is displayed, "Manual", "Fish" or "Meat" can be selected with the slider operation.

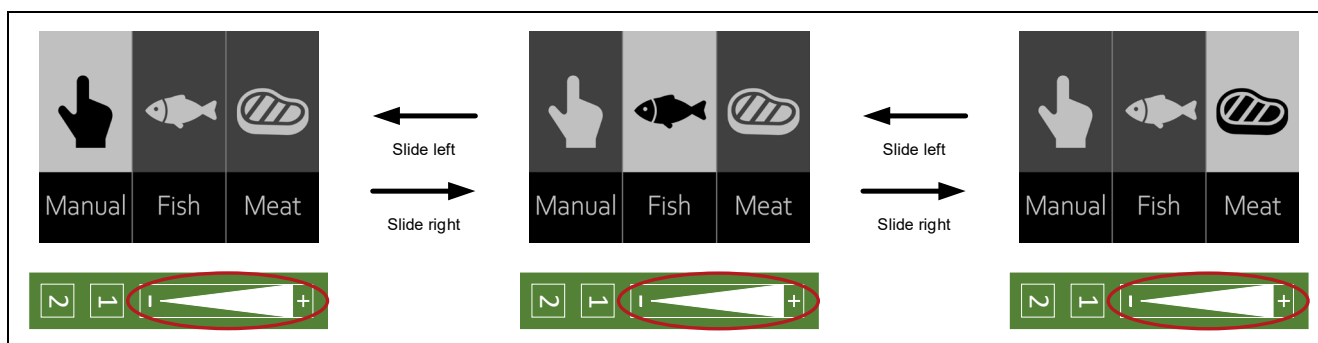


Figure 6-13 How to operate the Defrost mode selection screen

6.4.3 Select Manual

While "Manual" is selected on the Defrost mode selection screen, touching the "2" button can move to the Defrost detail setting screen.

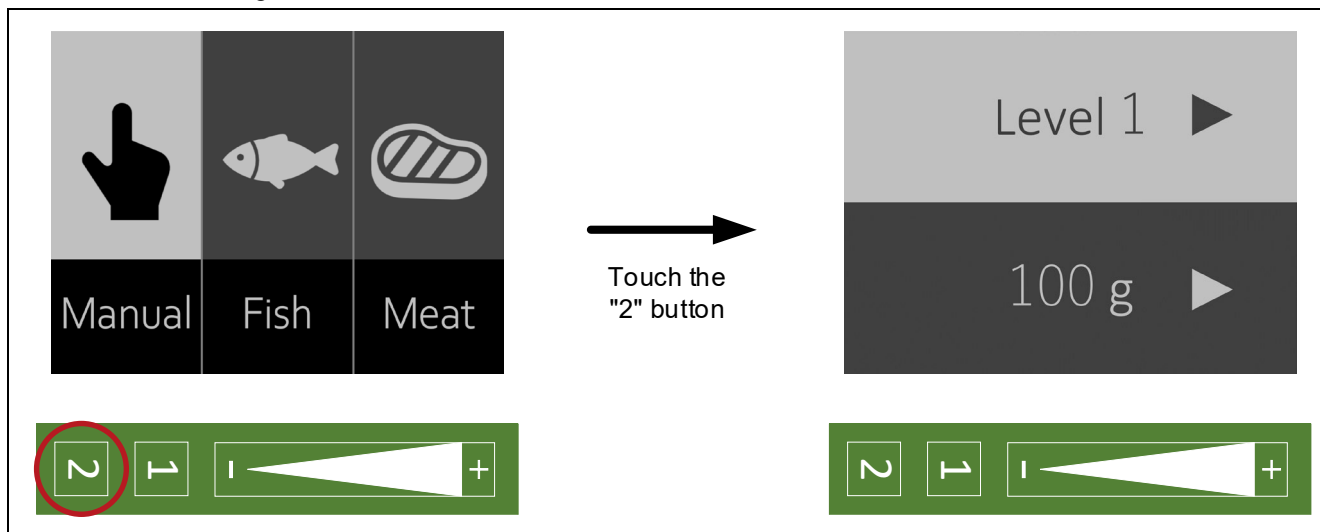


Figure 6-14 Move to the Defrost detail setting screen

6.4.3.1 Set the level of defrosting

While the cursor is on the upper side, the level of defrosting can be set with the slider. "Level1", "Level2" and "Level3" can be selected as the defrosting level.

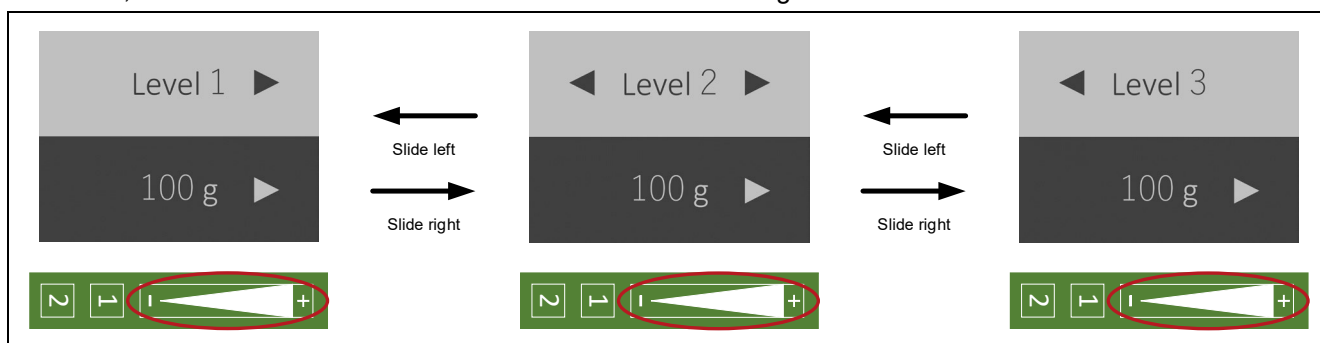


Figure 6-15 Setting the level of defrosting

6.4.3.2 Move the cursor

While the Defrost detail setting screen is displayed, touching the "2" button can move the cursor. The item with a light-colored background is selected.

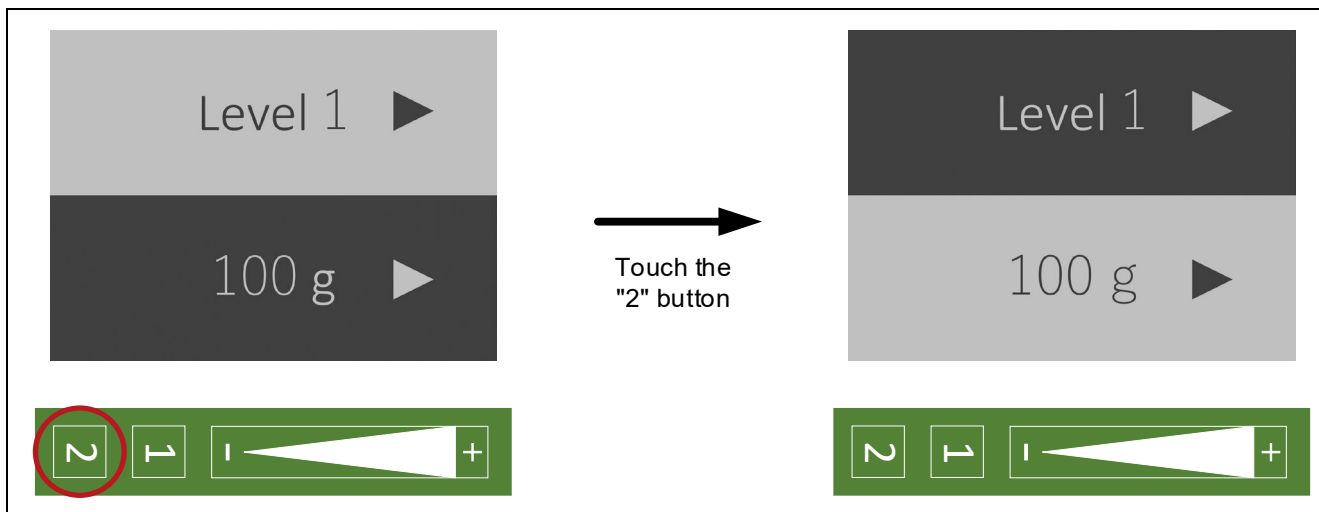


Figure 6-16 How to operate the cursor on the Defrost detail setting screen

6.4.3.3 Set the number of grams

While the cursor is on the lower side, the number of grams can be set with the slider. "100g", "200g" and "300g" can be selected as the defrosting amount.

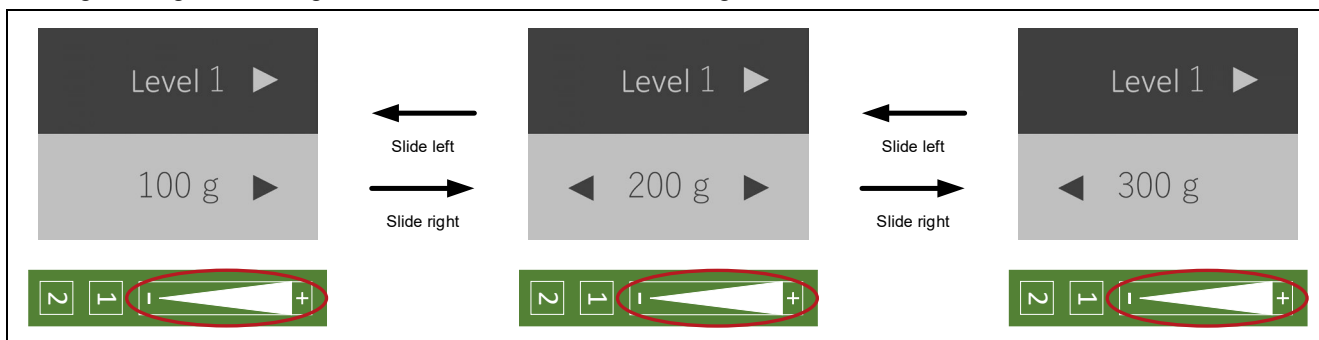


Figure 6-17 Setting the number of grams

6.4.3.4 Start defrosting

While the Defrost detail setting screen is displayed and the cursor is on the lower side, touching the "2" button can start defrosting.

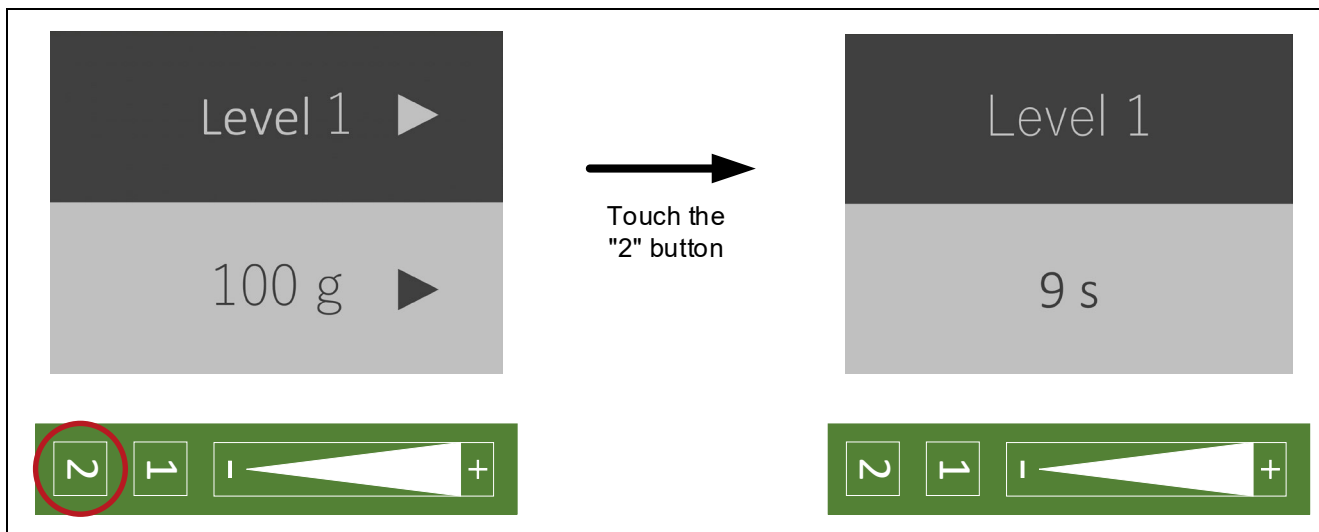


Figure 6-18 Start defrosting

6.4.4 Select Fish

While "Fish" is selected on the Defrost mode selection screen, touching the "2" button can start defrosting with the settings for "Fish".

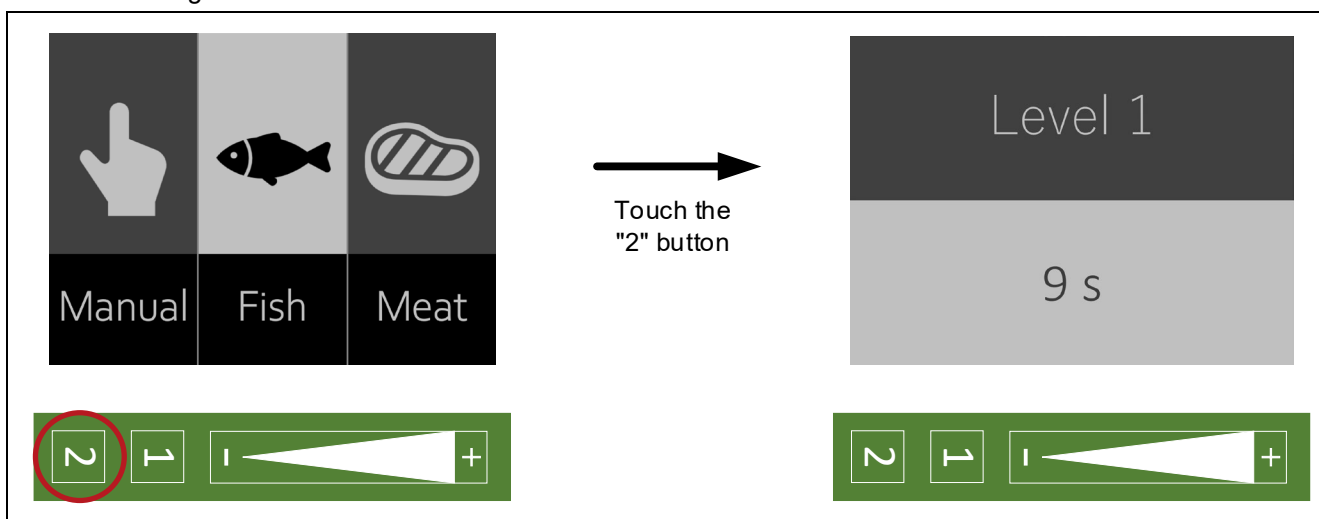


Figure 6-19 Start defrosting in Fish mode

6.4.5 Select Meat

While "Meat" is selected on the Defrost mode selection screen, touching the "2" button can start defrosting with the settings for "Meat".

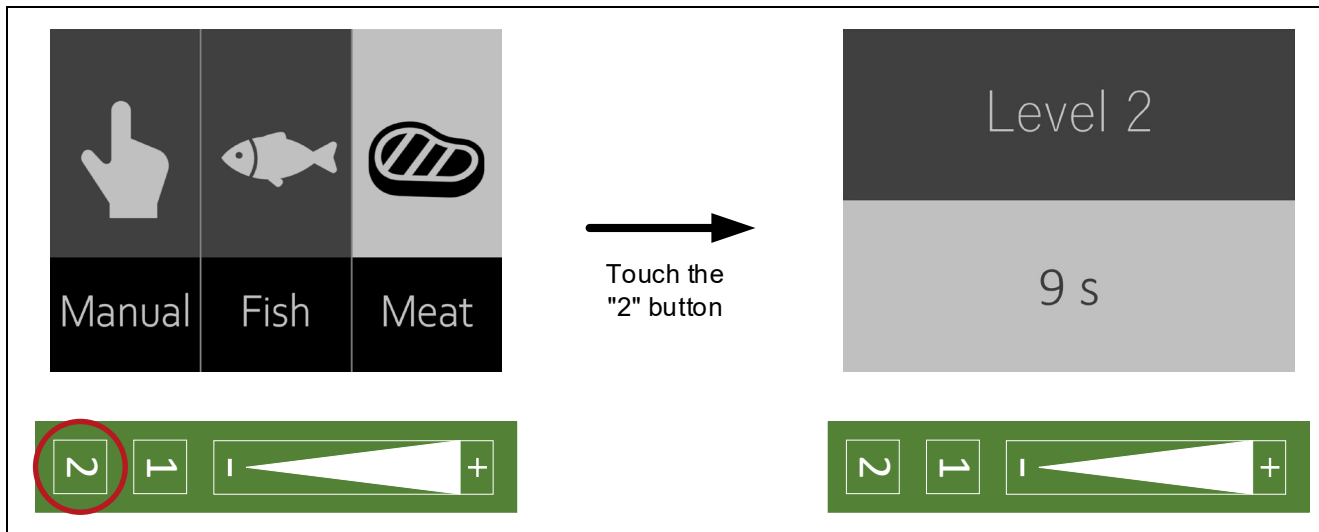


Figure 6-20 Start defrosting in Meat mode

6.5 Recipe setting

6.5.1 Move to recipe selection screen

While "Recipe" is selected on the menu screen, touching the "2" button can move to the Recipe selection screen.

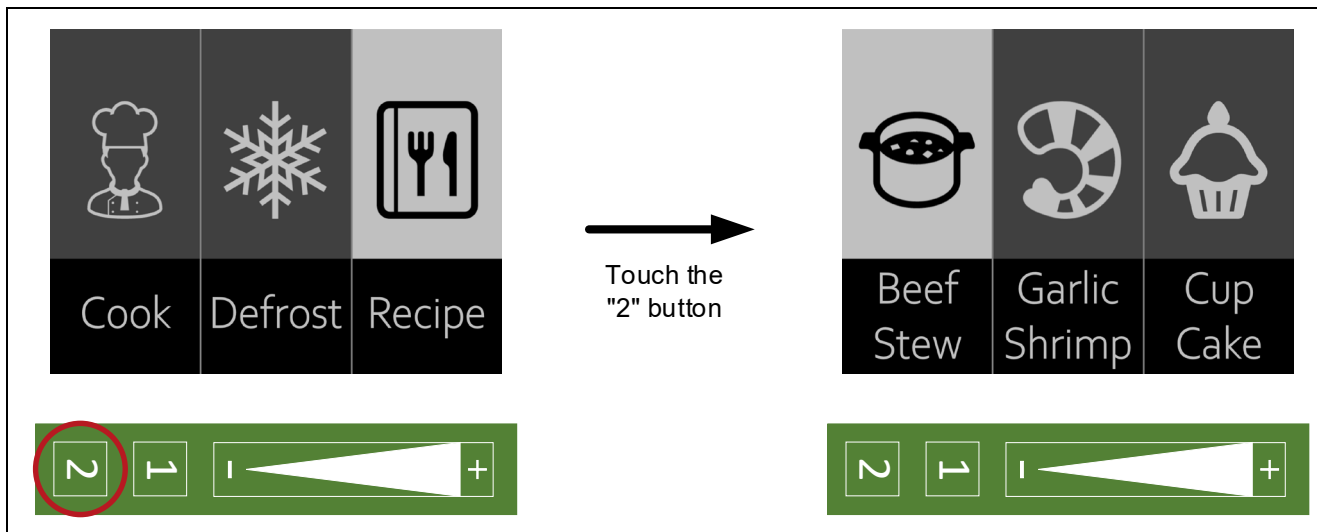


Figure 6-21 Move to the Recipe selection screen

6.5.2 Select recipe

While the Recipe selection screen is displayed, "Beef Stew", "Garlic Shrimp" or "Cup Cake" can be selected with the slider operation.



Figure 6-22 How to operate the Recipe selection screen

6.5.3 Select Beef Stew

While "Beef Stew" is selected on the Recipe selection screen, touching the "2" button can start cooking for the Settings for Beef Stew.

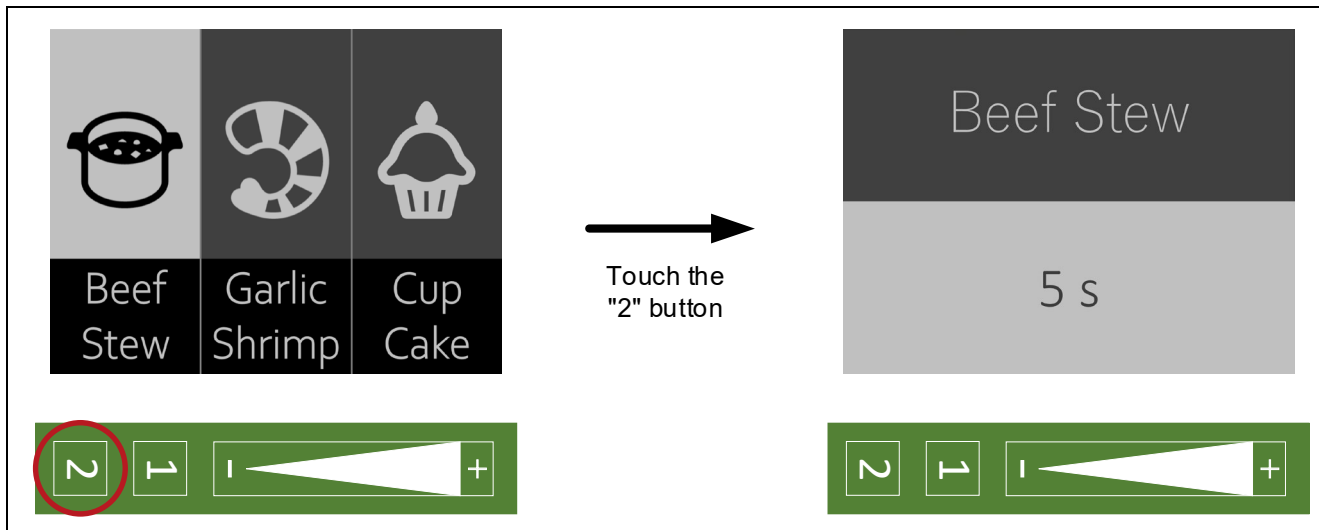


Figure 6-23 Start cooking in Beef Stew mode

6.5.4 Select Garlic Shrimp

While "Garlic Shrimp" is selected on the Recipe selection screen, touching the "2" button can start cooking for the Settings for Garlic Shrimp.

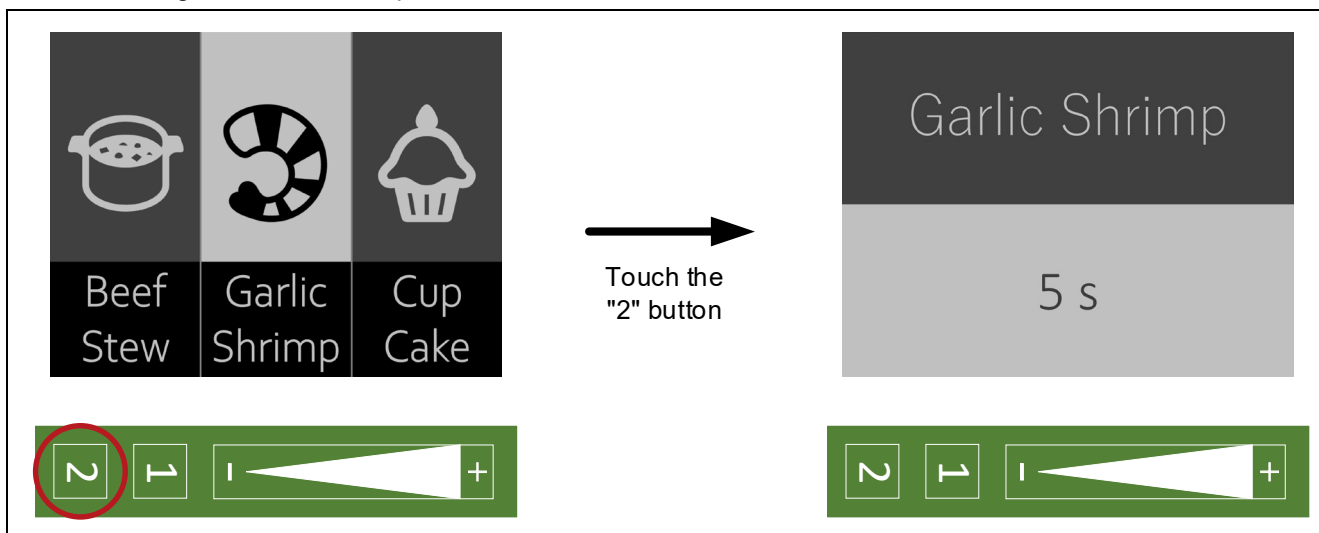


Figure 6-24 Start cooking in Garlic Shrimp mode

6.5.5 Select Cup Cake

While "Cup Cake" is selected on the Recipe selection screen, touching the "2" button can start cooking for the Settings for Cup Cake.

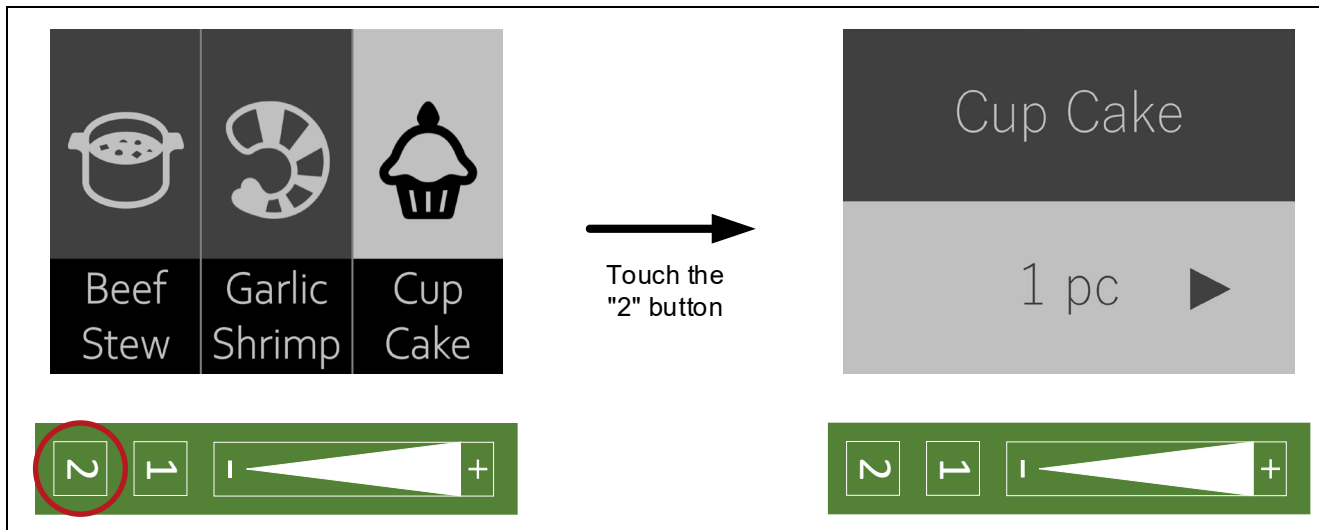


Figure 6-25 Move to the Cup Cake detail setting screen

6.5.5.1 Set the number of cupcakes

You can set the number of cupcakes with the slider.

"1pc", "2pcs" and "3pcs" can be selected as the cooking amount.

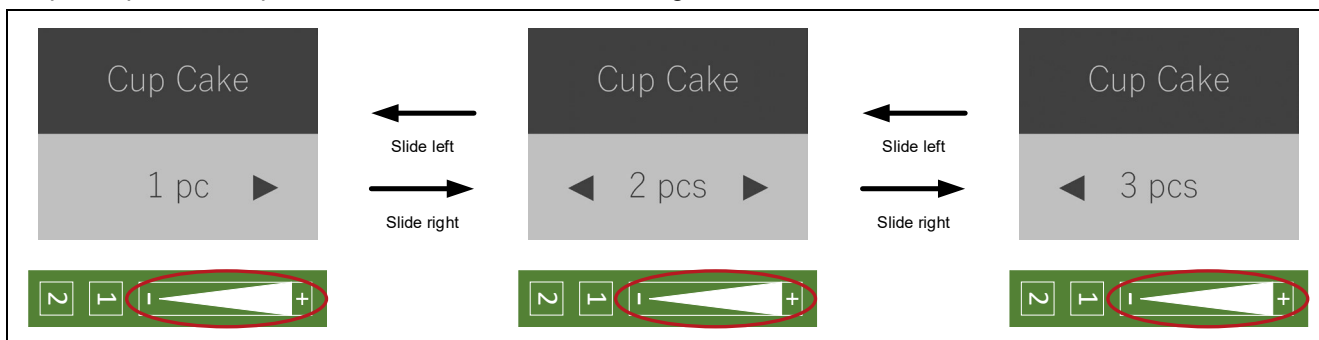


Figure 6-26 Setting the number of cupcakes

6.5.5.2 Start cooking

While the Cup Cake detail setting screen is displayed, touching the "2" button can start cooking.

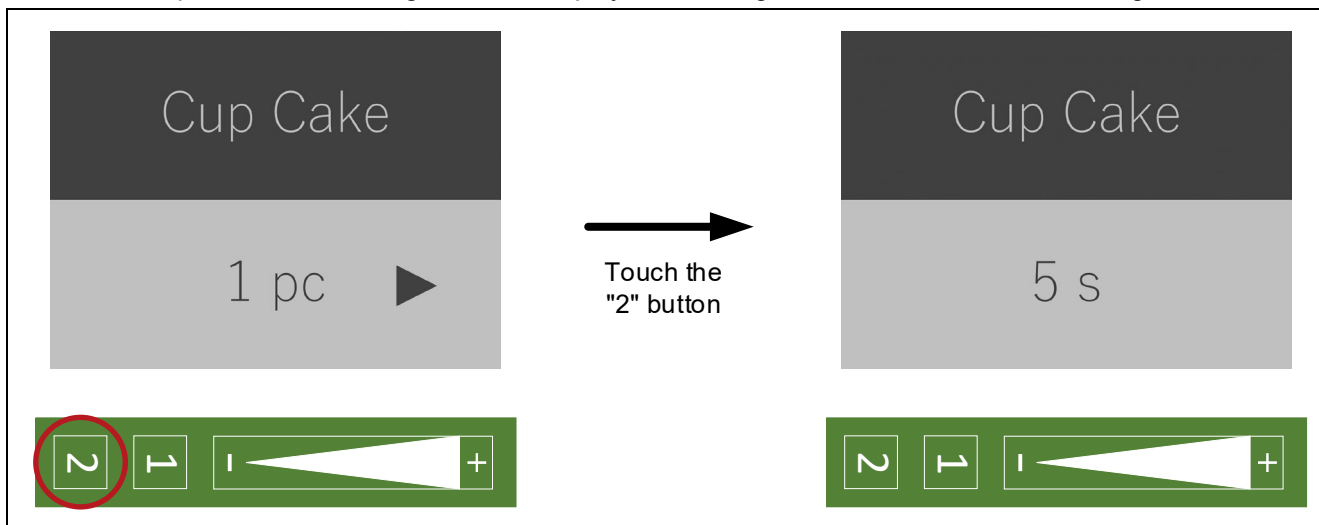


Figure 6-27 Start cooking in Cup Cake mode

6.6 About the "1" button

The "1" button returns to the menu screen from any screen.

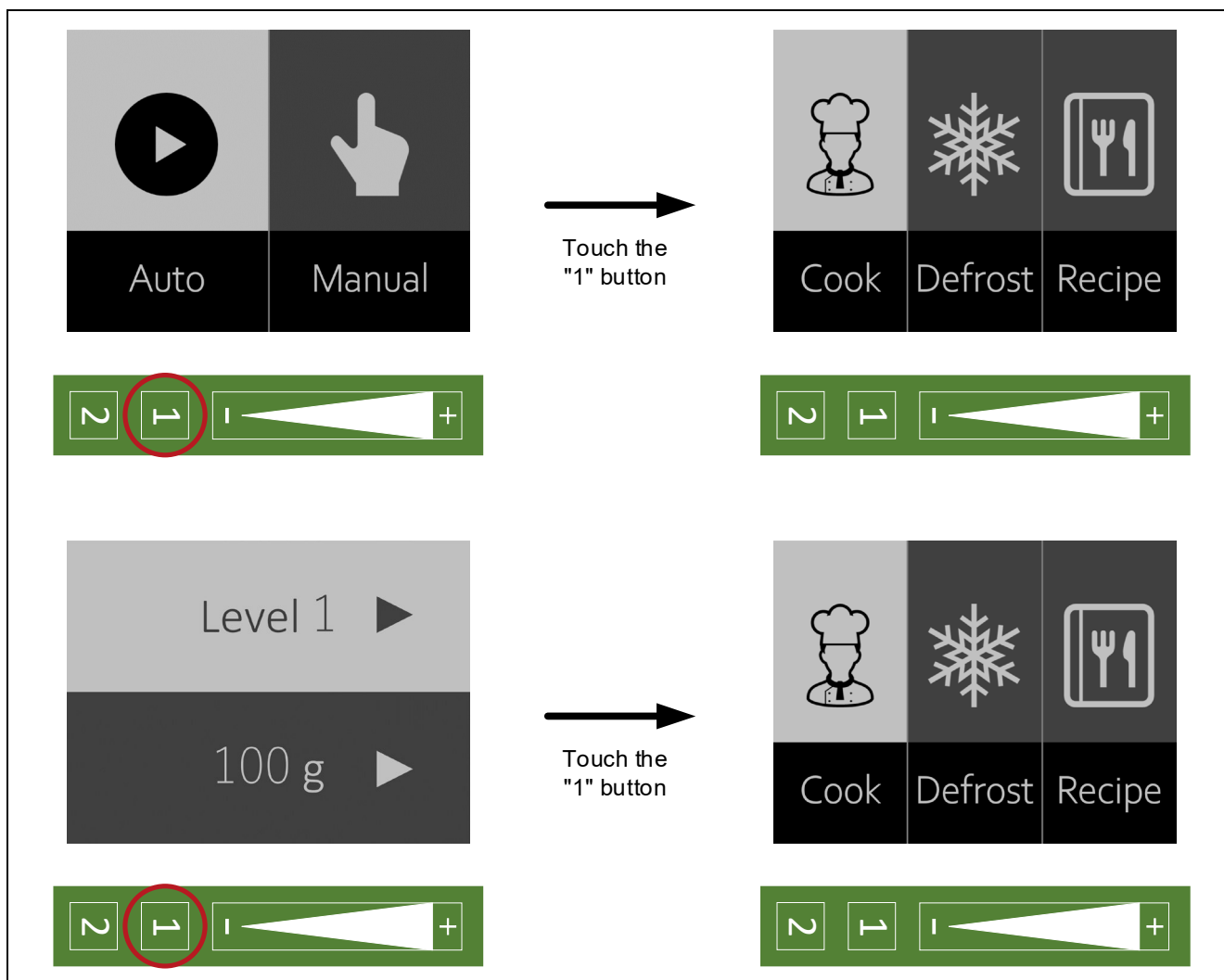


Figure 6-28 Example of "1" button operation

6.7 About the cooking completion screen

While completed cooking, the cooking completion screen is displayed for 3 seconds. After that, move to the menu screen automatically.

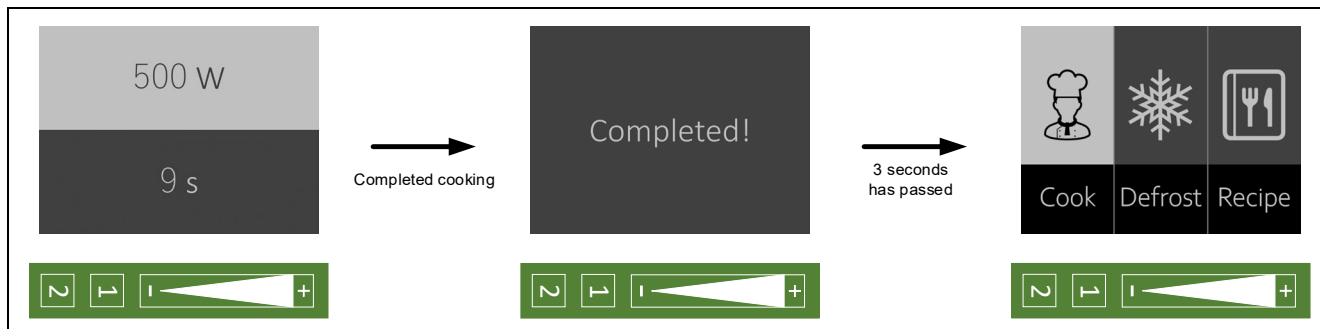


Figure 6-29 Example of cooking completion operation

6.8 Smart wakeup function

If no touch operation is performed for 10 seconds, the LCD is turned off and the RX140 transitions to software standby mode. For detail on Smart Wakeup, refer to "RX140 Group Smart Wakeup Solution".

Long touch any button to return to the previous screen.

7. Reference Documents

- RX140 Group User's Manual: Hardware (R01UH0905)
- RX140 Group Smart Wakeup Solution (R11AN0613)
- RX Family Using QE and FIT to Develop Capacitive Touch Applications (R01AN4516)
- RX Family QE for Display GUI Display Application Development Guide (R20AN0688)
- RX140 Group Renesas Starter Kit for RX140 User's Manual (R20UT5026)

The latest version can be downloaded from the Renesas Electronics website.

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Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Apr.24.23	—	First edition

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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